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# UE910 3G HARDWARE USER GUIDE

# APPLICABILITY TABLE

## PRODUCTS

■ ■ UE910-N3G

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# 1 INTRODUCTION

## 1.1 Scope

The aim of this document is the description of some hardware solutions useful for developing a product with the Telit UE910 module.

## 1.2 Audience

This document is intended for Telit customers, who are integrators, about to implement their applications using our UE910 modules.

## 1.3 Contact Information, Support

For general contact, technical support services, technical questions and report documentation errors contact Telit Technical Support at:

[TS-EMEA@telit.com](mailto:TS-EMEA@telit.com)

[TS-AMERICAS@telit.com](mailto:TS-AMERICAS@telit.com)

[TS-APAC@telit.com](mailto:TS-APAC@telit.com)

Alternatively, use:

<http://www.telit.com/support>

For detailed information about where you can buy the Telit modules or for recommendations on accessories and components visit:

<http://www.telit.com>

Our aim is to make this guide as helpful as possible. Keep us informed of your comments and suggestions for improvements.

Telit appreciates feedback from the users of our information.



## 1.4 List of acronyms

Acronym	Description
TTSC	Telit Technical Support Centre
USB	Universal Serial Bus
HS	High Speed
DTE	Data Terminal Equipment
UMTS	Universal Mobile Telecommunication System
WCDMA	Wideband Code Division Multiple Access
HSDPA	High Speed Downlink Packet Access
HSUPA	High Speed Uplink Packet Access
UART	Universal Asynchronous Receiver Transmitter
HSIC	High Speed Inter Chip
SIM	Subscriber Identification Module
SPI	Serial Peripheral Interface
ADC	Analog – Digital Converter
DAC	Digital – Analog Converter
I/O	Input Output
GPIO	General Purpose Input Output
CMOS	Complementary Metal – Oxide Semiconductor
MOSI	Master Output – Slave Input
MISO	Master Input – Slave Output
CLK	Clock
MRDY	Master Ready
SRDY	Slave Ready
CS	Chip Select
RTC	Real Time Clock
PCB	Printed Circuit Board
ESR	Equivalent Series Resistance
VSWR	Voltage Standing Wave Ratio
VNA	Vector Network Analyzer

## 1.5 Text Conventions

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Danger – This information **MUST** be followed or catastrophic equipment failure or bodily injury may occur.

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Caution or Warning – Alerts the user to important points about integrating the module, if these points are not followed, the module and end user equipment may fail or malfunction.

---



Tip or Information – Provides advice and suggestions that may be useful when integrating the module.

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All dates are in ISO 8601 format, i.e. YYYY-MM-DD.

## 1.6. Related Documents

- |  |               |
|--|---------------|
| • Digital Voice Interface Application Note | 80000NT10050A |
| • SPI Port Application Note                | 80000NT10053A |
| • SIM Holder Design Guides                 | 80000NT10001a |
| • USB HSIC Port Application Note           | 80000NT10071A |
| • AT Commands Reference Guide              | 80378ST10091A |
| • Telit EVK2 User Guide                    | 1vv0300704    |

## 2 OVERVIEW

The aim of this document is the description of some hardware solutions useful for developing a product with the Telit UE910 3G module.

In this document all the basic functions of a mobile phone will be taken into account; for each one of them a proper hardware solution will be suggested and eventually the wrong solutions and common errors to be avoided will be evidenced. Obviously this document cannot embrace the whole hardware solutions and products that may be designed. The wrong solutions to be avoided shall be considered as mandatory, while the suggested hardware configurations shall not be considered mandatory, instead the information given shall be used as a guide and a starting point for properly developing your product with the Telit UE910 module. For further hardware details that may not be explained in this document refer to the Telit UE910 Product Description document where all the hardware information is reported.



### NOTICE:

(EN) The integration of the WCDMA **UE910** cellular module within user application shall be done according to the design rules described in this manual.

(IT) L'integrazione del modulo cellulare WCDMA **UE910** all'interno dell'applicazione dell'utente dovrà rispettare le indicazioni progettuali descritte in questo manuale.

(DE) Die Integration des **UE910** WCDMA Mobilfunk-Moduls in ein Gerät muß gemäß der in diesem Dokument beschriebenen Konstruktionsregeln erfolgen.

(SL) Integracija WCDMA **UE910** modula v uporabniški aplikaciji bo morala upoštevati projektna navodila, opisana v tem priročniku.

(SP) La utilización del modulo WCDMA **UE910** debe ser conforme a los usos para los cuales ha sido diseñado descritos en este manual del usuario.

(FR) L'intégration du module cellulaire WCDMA **UE910** dans l'application de l'utilisateur sera faite selon les règles de conception décrites dans ce manuel.

(HE) האינטגרציה של המודול הסלולרי **UE910** עם המוצר.  
האינטגרציה מתבקש ליישם את ההנחיות המפורטות במסמך זה בתהליך האינטגרציה של המודם הסלולרי.

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# 3 PINS ALLOCATION

## 3.1 Pin-out

Pin	Signal	I/O	Function	Type	Comment
<b>USB HS 2.0 COMMUNICATION PORT</b>					
B15	USB_D+	I/O	USB differential Data (+)	-	
C15	USB_D-	I/O	USB differential Data (-)	-	
A13	VUSB	I	Power sense for the internal USB transceiver.	-	
<b>Asynchronous Serial Port (USIF0) - Prog. / Data + HW Flow Control</b>					
N15	C103/TXD	I	Serial data input from DTE	CMOS 1.8V	
M15	C104/RXD	O	Serial data output to DTE	CMOS 1.8V	
M14	C108/DTR	I	Input for (DTR) from DTE	CMOS 1.8V	
L14	C105/RTS	I	Input for Request to send signal (RTS) from DTE	CMOS 1.8V	
P15	C106/CTS	O	Output for Clear to Send signal (CTS) to DTE	CMOS 1.8V	
N14	C109/DCD	O	Output for (DCD) to DTE	CMOS 1.8V	
P14	C107/DSR	O	Output for (DSR) to DTE	CMOS 1.8V	
R14	C125/RING	O	Output for Ring (RI) to DTE	CMOS 1.8V	
<b>Asynchronous Auxiliary Serial Port (USIF1)</b>					
D15	TX_AUX	O	Auxiliary UART (TX Data to DTE)	CMOS 1.8V	
E15	RX_AUX	I	Auxiliary UART (RX Data from DTE)	CMOS 1.8V	
<b>USB HSIC</b>					
A12	HSIC_USB_DATA	I/O	USB HSIC data signal	CMOS 1.2V	
A11	HSIC_USB_STRB	I/O	USB HSIC strobe signal	CMOS 1.2V	
H15	HSIC_SLAVE_WAKEUP	I	Slave Wake Up	CMOS 1.8V	Shared with SPI_MRDI
F15	HSIC_HOST_WAKEUP	O	Host Wake Up	CMOS 1.8V	Shared with SPI_CLK
K15	HSIC_SUSPEND_REQUEST	O	Slave Suspend Request	CMOS 1.8V	Shared with GPIO08
J15	HSIC_HOST_ACTIVE	I	Active Host Indication	CMOS 1.8V	Shared with SPI_SRDI
<b>SIM card interface</b>					

<b>A6</b>	SIMCLK	O	External SIM signal – Clock	1.8 / 3V	
<b>A7</b>	SIMRST	O	External SIM signal – Reset	1.8 / 3V	
<b>A5</b>	SIMIO	I/O	External SIM signal – Data I/O	1.8 / 3V	
<b>A4</b>	SIMIN	I	External SIM signal – Presence (active low)	CMOS 1.8	
<b>A3</b>	SIMVCC	-	External SIM signal – Power supply for the SIM	1.8 / 3V	
<b>Analog Audio</b>					
<b>B2</b>	EAR+	O	Analog Audio Interface (EAR+)		
<b>B3</b>	EAR-	O	Analog Audio Interface (EAR-)		
<b>B4</b>	MIC+	I	Analog Audio Interface (MIC+)		
<b>B5</b>	MIC-	I	Analog Audio Interface (MIC-)		
<b>Digital Voice Interface (DVI)</b>					
<b>B9</b>	DVI_WA0	I/O	Digital Audio Interface (WA0)	CMOS 1.8V	
<b>B6</b>	DVI_RX	I/O	Digital Audio Interface (RX)	CMOS 1.8V	
<b>B7</b>	DVI_TX	I/O	Digital Audio Interface (TX)	CMOS 1.8V	
<b>B8</b>	DVI_CLK	I/O	Digital Audio Interface (CLK)	CMOS 1.8V	
<b>SPI</b>					
<b>D15</b>	SPI_MOSI	I	SPI MOSI	CMOS 1.8V	Shared with TX_AUX
<b>E15</b>	SPI_MISO	O	SPI_MISO	CMOS 1.8V	Shared with RX_AUX
<b>F15</b>	SPI_CLK	I	SPI Clock	CMOS 1.8V	
<b>H15</b>	SPI_MRDY	I	SPI_MRDY	CMOS 1.8V	
<b>J15</b>	SPI_SRDY	O	SPI_SRDY	CMOS 1.8V	
<b>DIGITAL IO</b>					
<b>C8</b>	GPIO_01	I/O	GPIO_01 /STAT LED	CMOS 1.8V	Alternate Function STAT LED
<b>C9</b>	GPIO_02	I/O	GPIO_02	CMOS 1.8V	
<b>C10</b>	GPIO_03	I/O	GPIO_03	CMOS 1.8V	
<b>C11</b>	GPIO_04	I/O	GPIO_04	CMOS 1.8V	
<b>B14</b>	GPIO_05	I/O	GPIO_05	CMOS 1.8V	
<b>C12</b>	GPIO_06	I/O	GPIO_06	CMOS 1.8V	
<b>C13</b>	GPIO_07	I/O	GPIO_07	CMOS 1.8V	
<b>K15</b>	GPIO_08	I/O	GPIO_08	CMOS 1.8V	

L15	GPIO_09	I/O	GPIO_09	CMOS 1.8V	
G15	GPIO_10	I/O	GPIO_10	CMOS 1.8V	
<b>ADC</b>					
B1	ADC_IN1	AI	Analog / Digital converter input	A/D	Accepted values 0 to 1.2V DC
<b>RF SECTION</b>					
K1	ANTENNA	I/O	WCDMA Antenna (50 ohm)	RF	
<b>Miscellaneous Functions</b>					
R13	HW_SHUTDOWN*	I	HW Unconditional Shutdown	CMOS 1.8V	Active low
R12	ON_OFF*	I	Input command for power ON	CMOS 1.8V	Active low
C14	VRTC	I	VRTC Backup capacitor	Power	backup for the embedded RTC supply
R11	VAUX/PWRMON	O	Supply Output for external accessories / Power ON Monitor	1.8V	
<b>Power Supply</b>					
M1	VBATT	-	Main power supply (Baseband)	Power	
M2	VBATT	-	Main power supply (Baseband)	Power	
N1	VBATT_PA	-	Main power supply (Radio PA)	Power	
N2	VBATT_PA	-	Main power supply (Radio PA)	Power	
P1	VBATT_PA	-	Main power supply (Radio PA)	Power	
P2	VBATT_PA	-	Main power supply (Radio PA)	Power	
E1	GND	-	Ground	Power	
G1	GND	-	Ground	Power	
H1	GND	-	Ground	Power	
J1	GND	-	Ground	Power	
L1	GND	-	Ground	Power	
A2	GND	-	Ground	Power	
E2	GND	-	Ground	Power	
F2	GND	-	Ground	Power	
G2	GND	-	Ground	Power	
H2	GND	-	Ground	Power	
J2	GND	-	Ground	Power	
K2	GND	-	Ground	Power	

<b>L2</b>	GND	-	Ground	Power
<b>R2</b>	GND	-	Ground	Power
<b>M3</b>	GND	-	Ground	Power
<b>N3</b>	GND	-	Ground	Power
<b>P3</b>	GND	-	Ground	Power
<b>R3</b>	GND	-	Ground	Power
<b>D4</b>	GND	-	Ground	Power
<b>M4</b>	GND	-	Ground	Power
<b>N4</b>	GND	-	Ground	Power
<b>P4</b>	GND	-	Ground	Power
<b>R4</b>	GND	-	Ground	Power
<b>N5</b>	GND	-	Ground	Power
<b>P5</b>	GND	-	Ground	Power
<b>R5</b>	GND	-	Ground	Power
<b>N6</b>	GND	-	Ground	Power
<b>P6</b>	GND	-	Ground	Power
<b>R6</b>	GND	-	Ground	Power
<b>P8</b>	GND	-	Ground	Power
<b>R8</b>	GND	-	Ground	Power
<b>P9</b>	GND	-	Ground	Power
<b>P10</b>	GND	-	Ground	Power
<b>R10</b>	GND	-	Ground	Power
<b>M12</b>	GND	-	Ground	Power
<b>B13</b>	GND	-	Ground	Power
<b>P13</b>	GND	-	Ground	Power
<b>E14</b>	GND	-	Ground	Power
<b>RESERVED</b>				
<b>C1</b>	RESERVED	-	RESERVED	
<b>D1</b>	RESERVED	-	RESERVED	
<b>B2</b>	RESERVED	-	RESERVED	
<b>C2</b>	RESERVED	-	RESERVED	
<b>D2</b>	RESERVED	-	RESERVED	
<b>B3</b>	RESERVED	-	RESERVED	
<b>C3</b>	RESERVED	-	RESERVED	
<b>D3</b>	RESERVED	-	RESERVED	

<b>E3</b>	RESERVED	-	RESERVED
<b>F3</b>	RESERVED	-	RESERVED
<b>G3</b>	RESERVED	-	RESERVED
<b>H3</b>	RESERVED	-	RESERVED
<b>J3</b>	RESERVED	-	RESERVED
<b>K3</b>	RESERVED	-	RESERVED
<b>L3</b>	RESERVED	-	RESERVED
<b>B4</b>	RESERVED	-	RESERVED
<b>C4</b>	RESERVED	-	RESERVED
<b>B5</b>	RESERVED	-	RESERVED
<b>C5</b>	RESERVED	-	RESERVED
<b>C6</b>	RESERVED	-	RESERVED
<b>C7</b>	RESERVED	-	RESERVED
<b>N7</b>	RESERVED	-	RESERVED
<b>P7</b>	RESERVED	-	RESERVED
<b>N8</b>	RESERVED	-	RESERVED
<b>N9</b>	RESERVED	-	RESERVED
<b>A10</b>	RESERVED	-	RESERVED
<b>N10</b>	RESERVED	-	RESERVED
<b>N11</b>	RESERVED	-	RESERVED
<b>B12</b>	RESERVED	-	RESERVED
<b>D12</b>	RESERVED	-	RESERVED
<b>N12</b>	RESERVED	-	RESERVED
<b>P12</b>	RESERVED	-	RESERVED
<b>F14</b>	RESERVED	-	RESERVED
<b>G14</b>	RESERVED	-	RESERVED
<b>H14</b>	RESERVED	-	RESERVED
<b>J14</b>	RESERVED	-	RESERVED
<b>K14</b>	RESERVED	-	RESERVED
<b>N13</b>	RESERVED	-	RESERVED
<b>L13</b>	RESERVED	-	RESERVED
<b>J13</b>	RESERVED	-	RESERVED
<b>M13</b>	RESERVED	-	RESERVED
<b>K13</b>	RESERVED	-	RESERVED
<b>H13</b>	RESERVED	-	RESERVED



<b>G13</b>	RESERVED	-	RESERVED
<b>F13</b>	RESERVED	-	RESERVED
<b>B11</b>	RESERVED	-	RESERVED
<b>B10</b>	RESERVED	-	RESERVED
<b>A9</b>	RESERVED	-	RESERVED
<b>A8</b>	RESERVED	-	RESERVED
<b>D14</b>	RESERVED	-	RESERVED
<b>A14</b>	RESERVED	-	RESERVED
<b>D13</b>	RESERVED	-	RESERVED
<b>E13</b>	RESERVED	-	RESERVED
<b>F1</b>	RESERVED	-	RESERVED
<b>R9</b>	RESERVED	-	RESERVED
<b>R7</b>	RESERVED	-	RESERVED
<b>P11</b>	RESERVED	-	RESERVED



**WARNING:**  
Reserved pins must not be connected

If not used, almost all pins should be left disconnected. The only exceptions are the following pins:

PAD	Signal	Note
M1,M2,N1,N2,P1,P2	VBATT & VBATT_PA	
E1, G1, H1, J1, L1, A2, E2, F2, G2, H2 J2,K2,L2,R2,M3,N3,P3,R3,D4,M4, N4,P4,R4,N5,P5,R5,N6,P6,R6,P8, R8,P9,P10,R10,M12,B13,P13,E14	GND	
R12	ON/OFF*	
R13	HW_SHUTDOWN*	
B15	USB_D+	If not used should be connected to a Test Point or an USB connector
C15	USB_D-	If not used should be connected to a Test Point or an USB connector
A13	VUSB	If not used should be connected to a Test Point or an USB connector
N15	C103/TXD	If not used should be connected to a Test Point
M15	C104/RXD	If not used should be connected to a Test Point
L14	C105/RTS	If the flow control is not used it should be connected to GND
P15	C106/CTS	If not used should be connected to a Test Point
D15	TXD_AUX	If not used should be connected to a Test Point
E15	RXD_AUX	If not used should be connected to a Test Point
K1	MAIN ANTENNA	
A6	SIMCLK	
A7	SIMRST	
A5	SIMIO	
A4	SIMIN	

RTS pin should be connected to the GND (on the module side) if flow control is not used.

The above pins are also necessary to debug the application when the module is assembled on it so we recommend connecting them also to dedicated test point.

### 3.1.1 LGA Pads Layout

#### TOP VIEW

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	
1		ADC_IN1	RES	RES	GND	RES	GND	GND	GND	ANT	GND	VBATT	VBATT_PA	VBATT_PA		
2	GND	SPK+	RES	RES	GND	GND	GND	GND	GND	GND	GND	VBATT	VBATT_PA	VBATT_PA	GND	
3	SIMVC C	SPK -	RES	RES	RES	RES	RES	RES	RES	RES	RES	GND	GND	GND	GND	
4	SIMIN	MIC+	RES	GND								GND	GND	GND	GND	
5	SIMIO	MIC -	RES										GND	GND	GND	
6	SIMCLK	DVL_RX	RES										GND	GND	GND	
7	SIMRS T	DVL_TX	RES										RES	RES	RES	
8	RES	DVL_CLK	GPIO_0 1										RES	GND	GND	
9	RES	DVL_WA 0	GPIO_0 2										RES	GND	RES	
10	RES	RES	GPIO_0 3										RES	GND	GND	
11	HSIC_ USB_S TRB	RES	GPIO_0 4										RES	RES	VAUX/ PWRM ON	
12	HSIC_ USB_D ATA	RES	GPIO_0 6	RES								GND	RES	RES	ON_OF F*	
13	VUSB	GND	GPIO_0 7	RES	RES	RES	RES	RES	RES	RES	RES	RES	RES	RES	GND	HW_SH UTDO WN*
14	RES	GPIO_05	VRTC	RES	GND	RES	RES	RES	RES	RES	C105/R TS	C108/D TR	C109/D CD	C107/D SR	C125/R ING	
15		USB_D+	USB_D -	TX AUX	RX AUX	SPL_CLK	GPIO_1 0	SPLM RDY	SPLSR DY	GPIO_0 8	GPIO_0 9	C104/R XD	C103/T XD	C106/C TS		

# 4 POWER SUPPLY

The power supply circuitry and board layout are a very important part in the full product design and they strongly reflect on the product overall performances, hence read carefully the requirements and the guidelines that will follow for a proper design.

## 4.1 Power Supply Requirements

The external power supply must be connected to VBATT & VBATT\_PA signals and must fulfil the following requirements:

Power Supply	Value
Nominal Supply Voltage	3.8V
Normal Operating Voltage Range	3.40 V ÷ 4.20 V
Extended Operating Voltage Range	3.10 V ÷ 4.50 V



**NOTE:**

The Operating Voltage Range **MUST** never be exceeded; care must be taken when designing the application’s power supply section to avoid having an excessive voltage drop.

If the voltage drop is exceeding the limits it could cause a Power Off of the module.

The Power supply must be higher than 3.22 V to power on the module

Overshoot voltage (regarding MAX Extended Operating Voltage) and drop in voltage (regarding MIN Extended Operating Voltage) **MUST** never be exceeded;

The “Extended Operating Voltage Range” can be used only with completely assumption and application of the HW User guide suggestions.

## 4.2 Power Consumption

Mode	Average (mA)	Mode Description
Switched Off	180 uA	Module supplied but switched off
AT+CFUN=5	1.6	Disabled TX and RX; DRX7
WCDMA Voice	170	WCDMA voice call (TX = 10dBm)
WCDMA HSDPA (22dBm)	538	WCDMA data call (Cat 8, TX = 22dBm)



**NOTE:**

The electrical design for the Power supply should be made ensuring it will be capable of a peak current output of at least 1 A.

## 4.3 General Design Rules

The principal guidelines for the Power Supply Design embrace three different design steps:

- the electrical design
- the thermal design
- the PCB layout.

### 4.3.1 Electrical Design Guidelines

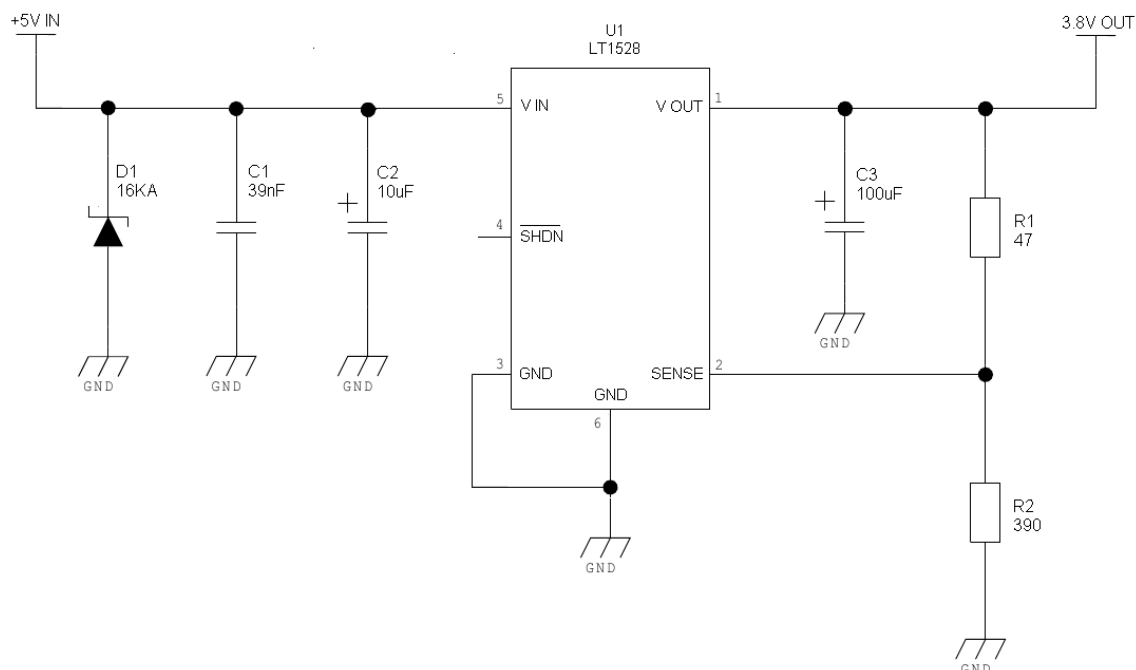
The electrical design of the power supply depends strongly from the power source where this power is drained. We will distinguish them into three categories:

- +5V input (typically PC internal regulator output)
- +12V input (typically automotive)
- Battery

#### 4.3.1.1 +5V Source Power Supply Design Guidelines

- The desired output for the power supply is 3.8V, hence there's not a big difference between the input source and the desired output and a linear regulator can be used. A switching power supply will not be suited because of the low drop out requirements.
- When using a linear regulator, a proper heat sink shall be provided in order to dissipate the power generated.
- A Bypass low ESR capacitor of adequate capacity must be provided in order to cut the current absorption peaks close to the Module, a 100 $\mu$ F capacitor is usually suited.
- Make sure the low ESR capacitor on the power supply output rated at least 10V.

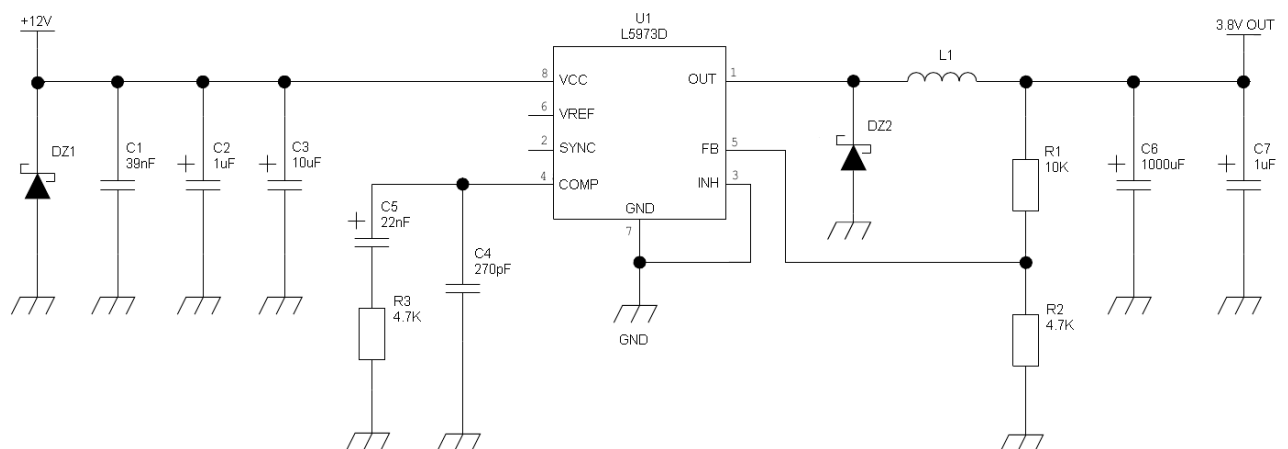
An example of linear regulator with 5V input is:



### 4.3.1.2 + 12V input Source Power Supply Design Guidelines

- The desired output for the power supply is 3.8V, hence due to the big difference between the input source and the desired output, a linear regulator is not suited and shall not be used. A switching power supply will be preferable because of its better efficiency.
- When using a switching regulator, a 500kHz or more switching frequency regulator is preferable because of its smaller inductor size and its faster transient response. This allows the regulator to respond quickly to the current peaks absorption.
- In any case the frequency and Switching design selection is related to the application to be developed due to the fact the switching frequency could also generate EMC interferences.
- For car PB battery the input voltage can rise up to 15,8V and this should be kept in mind when choosing components: all components in the power supply must withstand this voltage.
- A Bypass low ESR capacitor of adequate capacity must be provided in order to cut the current absorption peaks, a 100 $\mu$ F capacitor is usually suited.
- Make sure the low ESR capacitor on the power supply output is rated at least 10V.
- For Car applications a spike protection diode should be inserted close to the power input, in order to clean the supply from spikes.

An example of switching regulator with 12V input is in the below schematic:



### 4.3.1.3 Battery Source Power Supply Design Guidelines

The desired nominal output for the power supply is 3.8V and the maximum voltage allowed is 4.2V, hence a single 3.7V Li-Ion cell battery type is suited for supplying the power to the Telit UE910 module.

- A Bypass low ESR capacitor of adequate capacity must be provided in order to cut the current absorption peaks, a 100µF tantalum capacitor is usually suited.
- Make sure the low ESR capacitor (usually a tantalum one) is rated at least 10V.
- A protection diode should be inserted close to the power input, in order to save the UE910 from power polarity inversion. Otherwise the battery connector should be done in a way to avoid polarity inversions when connecting the battery.
- The battery capacity must be at least 500mAh in order to withstand the current peaks of 2A; the suggested capacity is from 500mAh to 1000mAh.



**WARNING:**

The three cells Ni/Cd or Ni/MH 3,6 V Nom. battery types or 4V PB types **MUST NOT BE USED DIRECTLY** since their maximum voltage can rise over the absolute maximum voltage for the UE910 and damage it.



**NOTE:**

DON'T USE any Ni-Cd, Ni-MH, and Pb battery types directly connected with UE910. Their use can lead to overvoltage on the UE910 and damage it. USE ONLY Li-Ion battery types.

---



#### 4.3.1.4 Thermal Design Guidelines

The thermal design for the power supply heat sink should be done with the following specifications:

- Average current consumption during HSDPA transmission @PWR level max : 700 mA
- Average current during idle: 1.8 mA

Considering the very low current during idle, especially if Power Saving function is enabled, it is possible to consider from the thermal point of view that the device absorbs current significantly only during calls.

If we assume that the device stays into transmission for short periods of time (let's say few minutes) and then remains for a quite long time in idle (let's say one hour), then the power supply has always the time to cool down between the calls and the heat sink could be smaller than the calculated one for 700mA maximum RMS current, or even could be the simple chip package (no heat sink).

Moreover in the average network conditions the device is requested to transmit at a lower power level than the maximum and hence the current consumption will be less than the 700mA, being usually around 150mA.

For these reasons the thermal design is rarely a concern and the simple ground plane where the power supply chip is placed can be enough to ensure a good thermal condition and avoid overheating. The generated heat will be mostly conducted to the ground plane under the UE910; you must ensure that your application can dissipate it.



**NOTE:**

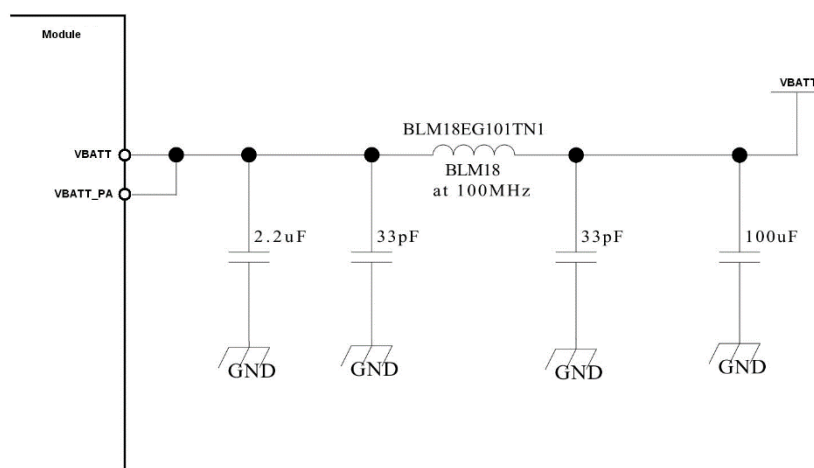
The average consumption during transmissions depends on the power level at which the device is requested to transmit by the network. The average current consumption hence varies significantly.

### 4.3.1.5 Power Supply PCB layout Guidelines

As seen on the electrical design guidelines the power supply shall have a low ESR capacitor on the output to cut the current peaks on the input to protect the supply from spikes. The placement of this component is crucial for the correct working of the circuitry. A misplaced component can be useless or can even decrease the power supply performances.

- The Bypass low ESR capacitor must be placed close to the Telit UE910 power input pads or in the case the power supply is a switching type it can be placed close to the inductor to cut the ripple provided the PCB trace from the capacitor to the UE910 is wide enough to ensure a dropless connection even during an 1A current peak.
- The protection diode must be placed close to the input connector where the power source is drained.
- The PCB traces from the input connector to the power regulator IC must be wide enough to ensure no voltage drops occur when an 1A current peak is absorbed.
- The PCB traces to the UE910 and the Bypass capacitor must be wide enough to ensure no significant voltage drops occur. This is for the same reason as previous point. Try to keep this trace as short as possible.
- To reduce the EMI due to switching, it is important to keep very small the mesh involved; thus the input capacitor, the output diode (if not embodied in the IC) and the regulator have to form a very small loop. This is done in order to reduce the radiated field (noise) at the switching frequency (100-500 kHz usually).
- A dedicated ground for the Switching regulator separated by the common ground plane is suggested.
- The placement of the power supply on the board should be done in such a way to guarantee that the high current return paths in the ground plane are not overlapped to any noise sensitive circuitry as the microphone amplifier/buffer or earphone amplifier.
- The power supply input cables should be kept separate from noise sensitive lines such as microphone/earphone cables.
- The insertion of EMI filter on VBATT pins is suggested in those designs where antenna is placed close to battery or supply lines. A ferrite bead like Murata BLM18EG101TN1 or Taiyo Yuden P/N FBMH1608HM101 can be used for this purpose.

The below figure shows the recommended circuit:



## 4.4 RTC Bypass out

The VRTC pin brings out the Real Time Clock supply, which is separate from the rest of the digital part, allowing having only RTC going on when all the other parts of the device are off.

To this power output a backup capacitor can be added in order to increase the RTC autonomy during power off of the battery. NO Devices must be powered from this pin.

In order to keep the RTC active when VBATT is not supplied it is possible to back up the RTC section connecting a **backup circuit** to the related VRTC signal (pad C14 on module's Pinout).

For additional details on the Backup solutions please refer to the related application note (xE910 RTC Backup Application Note)

## 4.5 VAUX Power Output

A regulated power supply output is provided in order to supply small devices from the module. The signal is present on Pad R11 and it is in common with the PWRMON (module powered ON indication) function.

This output is always active when the module is powered ON.

The operating range characteristics of the supply are:

Item	Min	Typical	Max
Output voltage	1.78V	1.80V	1.82V
Output current	-	-	60mA
Output bypass capacitor (inside the module)		1uF	

# 5 DIGITAL SECTION

## 5.1 Logic Levels Specification

### ABSOLUTE MAXIMUM RATINGS – NOT FUNCTIONAL:

Parameter	Min	Max
Input level on any digital pin (CMOS 1.8) with respect to ground	-0.3V	2.1V
Input level on any digital pin (CMOS 1.2) with respect to ground	-0.3V	1.4V

### OPERATING RANGE - INTERFACE LEVELS (1.8V CMOS):

Parameter	Min	Max
Input high level	1.5V	1.9V
Input low level	0V	0.35V
Output high level	1.6V	1.9V
Output low level	0V	0.2V

### OPERATING RANGE - INTERFACE LEVELS (1.2V CMOS):

Parameter	Min	Max
Input high level	0.9V	1.3V
Input low level	0V	0.3V
Output high level	1V	1.3V
Output low level	0V	0.1V

### CURRENT CHARACTERISTICS:

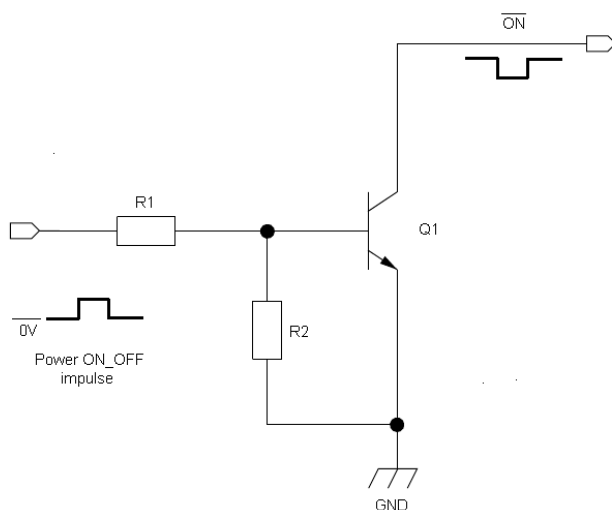
Parameter	AVG
Output Current	1mA
Input Current	1uA

## 5.2 Power on

To turn on the UE910 the pad ON\_OFF\* must be tied low for at least 5 seconds and then released.

The maximum current that can be drained from the ON\_OFF\* pad is 0,1 mA.

A simple circuit to do it is:



### NOTE:

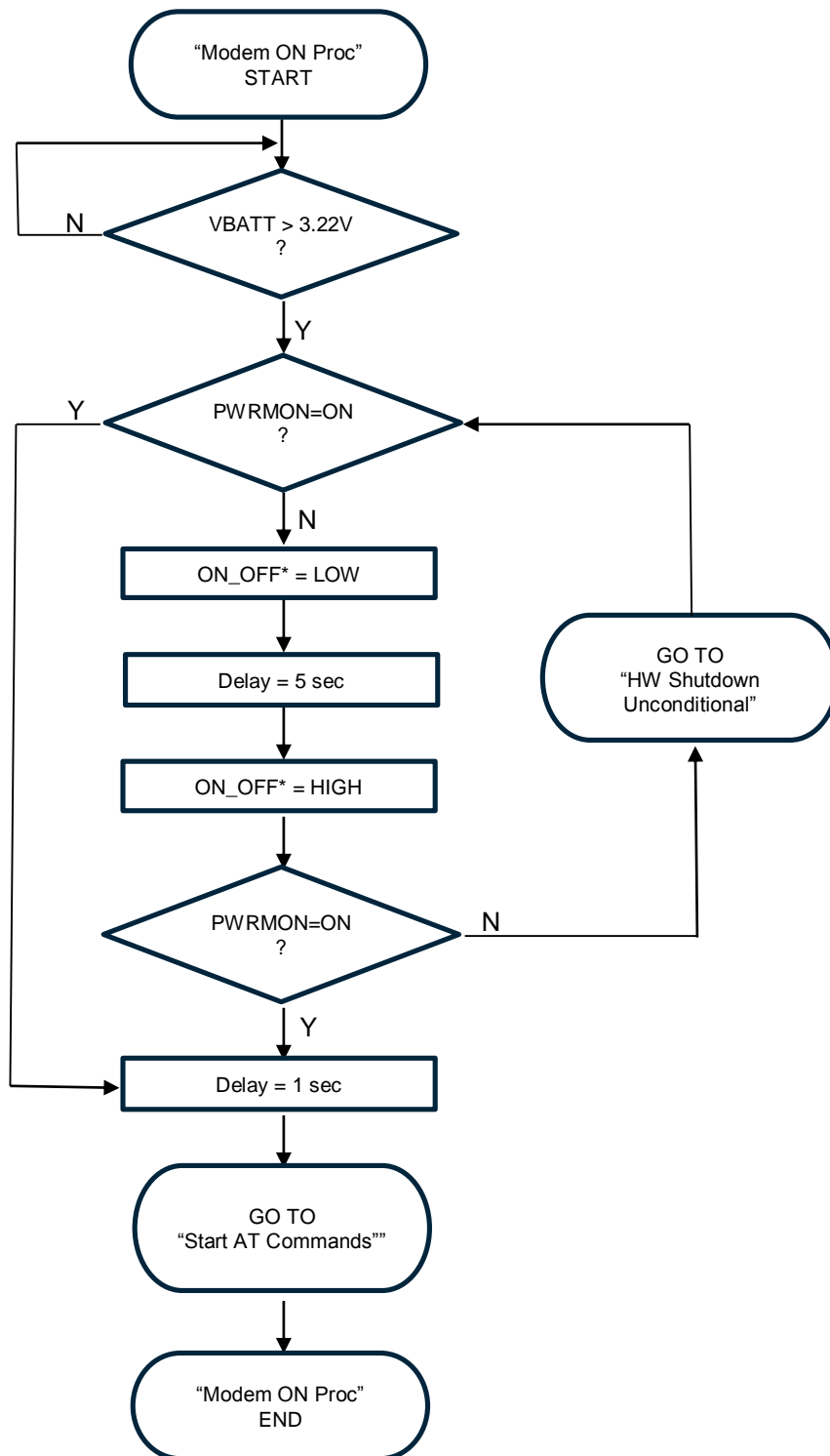
Don't use any pull up resistor on the ON\_OFF\* line, it is internally pulled up. Using pull up resistor may bring to latch up problems on the UE910 power regulator and improper power on/off of the module. The line ON\_OFF\* must be connected only in open collector or open drain configuration.

In this document all the lines that are inverted, hence have active low signals are labelled with a name that ends with "#", "\*" or with a bar over the name.

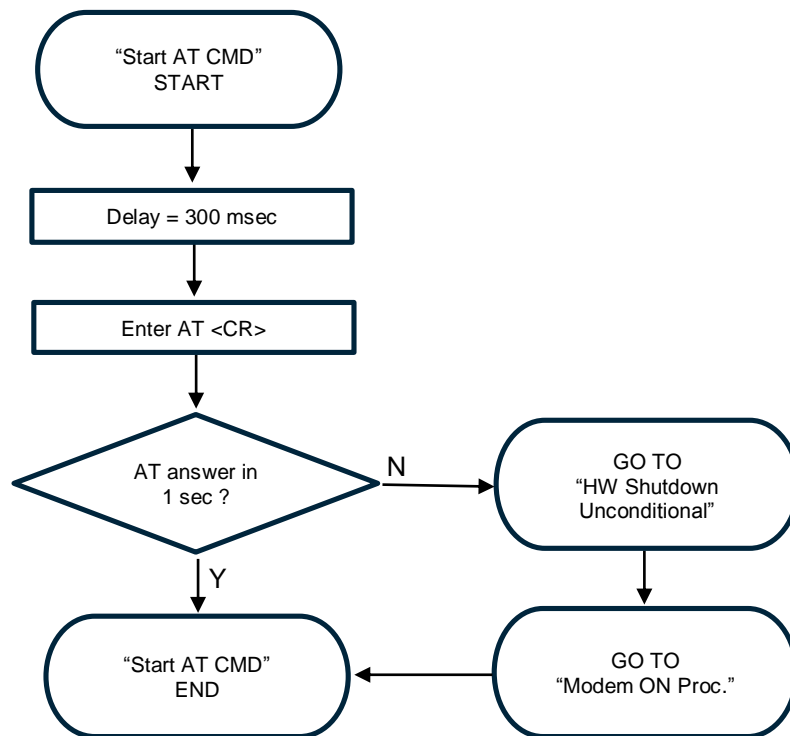
To check if the device has powered on, the hardware line PWRMON should be monitored.

It is mandatory to avoid sending data to the serial ports during the first 200ms of the module start-up.

A flow chart showing the proper turn on procedure is displayed below:



A flow chart showing the AT commands managing procedure is displayed below:

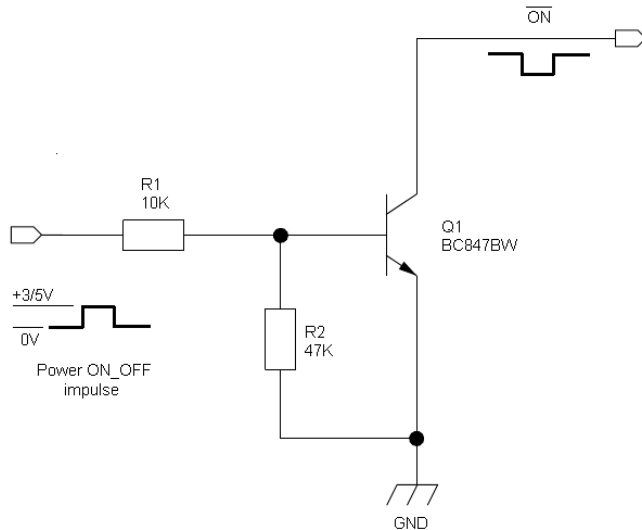


**NOTE:**

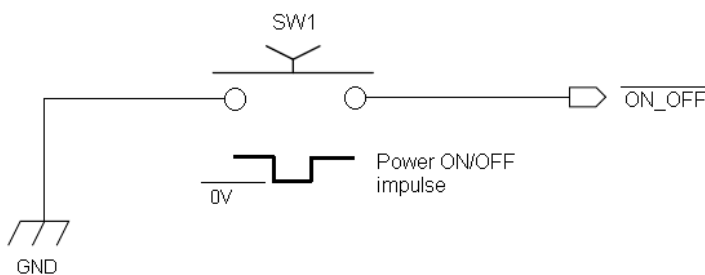
In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the UE910 when the module is powered off or during an ON/OFF transition.

For example:

1- Let's assume you need to drive the ON\_OFF\* pad with a totem pole output of a +3/5 V microcontroller (uP\_OUT1):



2- Let's assume you need to drive the ON\_OFF\* pad directly with an ON/OFF button:



**WARNING:**

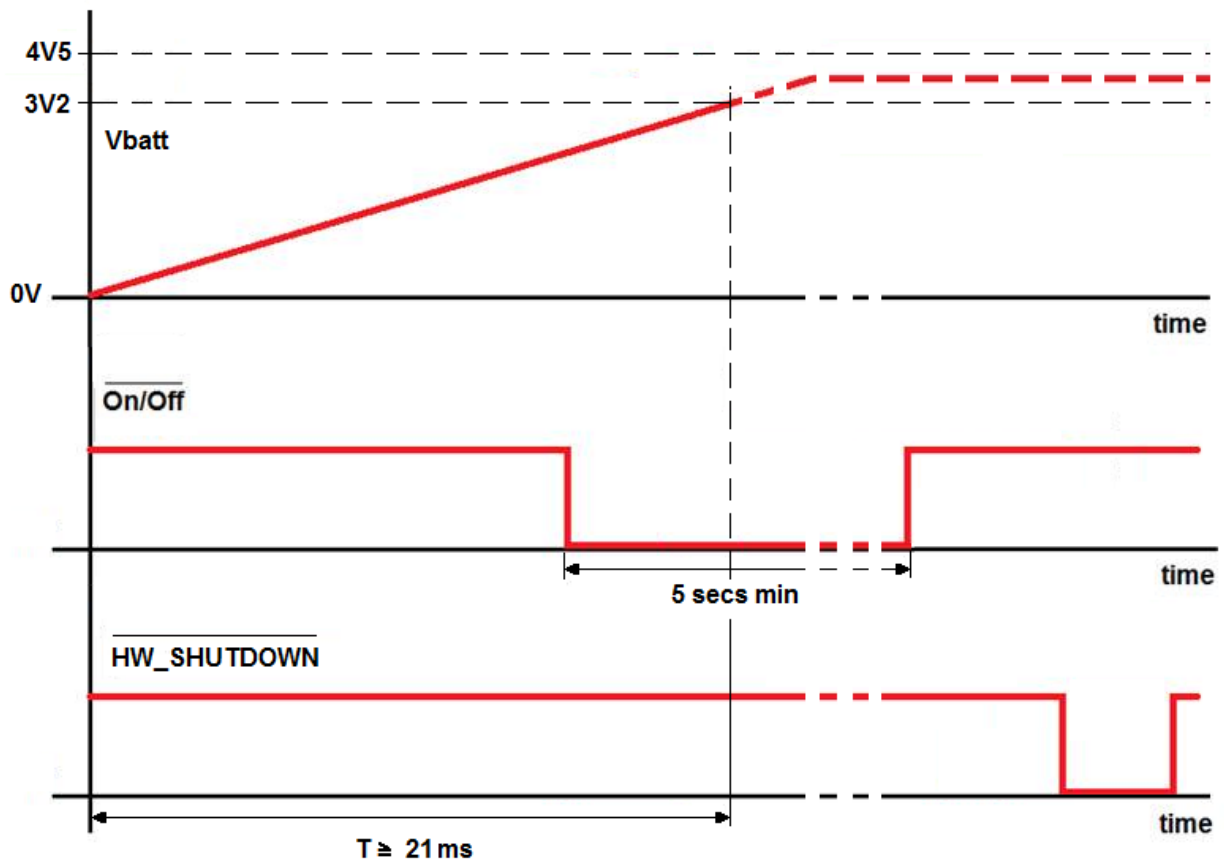
It is recommended to set the ON\_OFF\* line LOW to power on the module only after VBATT is higher than 3.22V.

In case this condition it is not satisfied you could use the HW\_SHUTDOWN\* line to recover it and then restart the power on activity using the ON\_OFF\* line.

An example of this is described in the following diagram.



Power ON diagram:



After HW\_SHUTDOWN\* is released you could again use the ON\_OFF\* line to power on the module.

## 5.3 Power off

Turning off the device can be done in two ways:

- via AT command (see UE910 Software User Guide, AT#SHDN)
- by tying low pin ON\_OFF\*

Either ways, the device issues a detach request to network informing that the device will not be reachable any more.

To turn OFF the UE910 the pad ON\_OFF\* must be tied low for at least 3 seconds and then released.



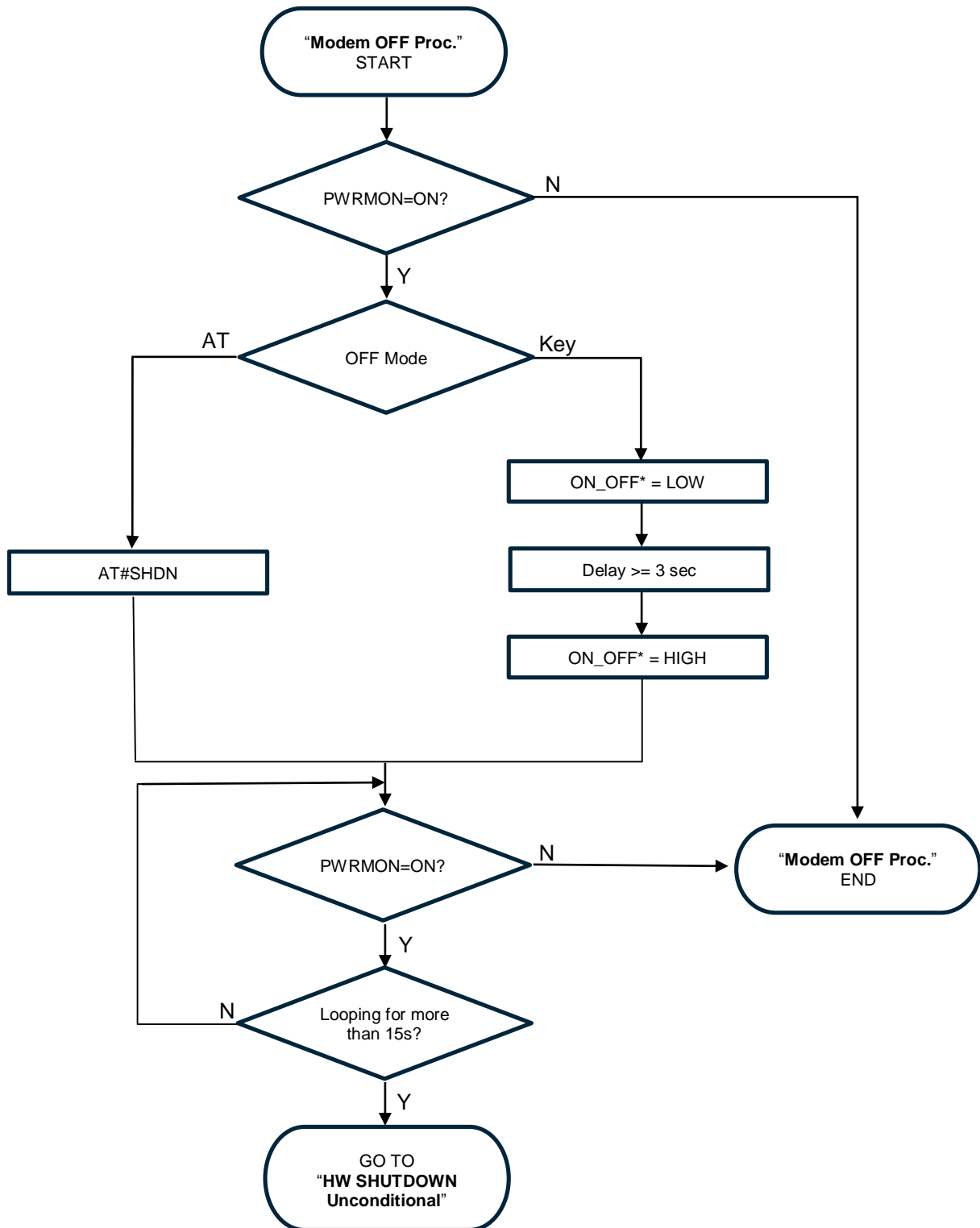
### NOTE:

To check if the device has been powered off, the hardware line PWRMON must be monitored. The device is powered off when PWRMON goes low.

In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the UE910 when the module is powered off or during an ON/OFF transition.

---

The following flow chart shows the proper turn off procedure:



## 5.4 Unconditional Shutdown

HW\_SHUTDOWN\* is used to unconditionally shutdown the UE910. Whenever this signal is pulled low, the UE910 is reset. When the device is reset it stops any operation. After the release of the line, the UE910 is unconditionally shut down, without doing any detach operation from the network where it is registered. This behaviour is not a proper shut down because any WCDMA device is requested to issue a detach request on turn off. The HW\_SHUTDOWN\* is internally controlled on start-up to achieve always a proper power-on reset sequence, so there's no need to control this pin on start-up. To unconditionally shutdown the UE910, the pad HW\_SHUTDOWN\* must be tied low for at least 200 milliseconds and then released.

The signal is internally pulled up so the pin can be left floating if not used.

If used, then it **must always be connected with an open collector transistor**, to permit to the internal circuitry the power on reset and under voltage lockout functions.

### PIN DESCRIPTION

Signal	Function	I/O	PAD
HW_SHUTDOWN*	Unconditional Shutdown of the Module	I	R13

### OPERATING LEVELS

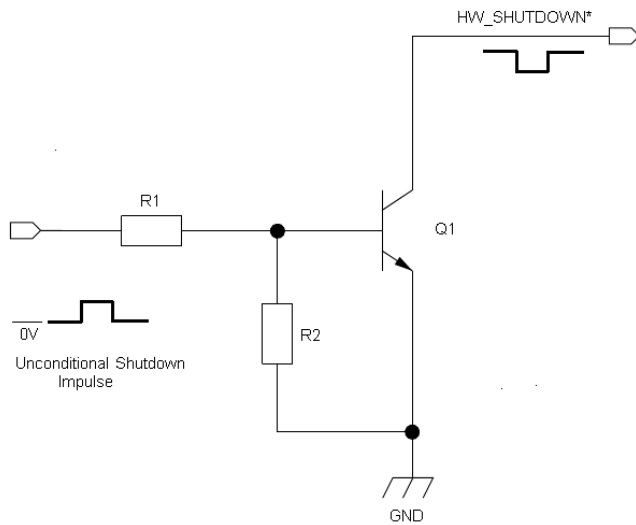
Signal Status	Min	Max
HW_SHUTDOWN* Input high	1.5V	1.9V
HW_SHUTDOWN* Input Low	0V	0.35V



#### WARNING:

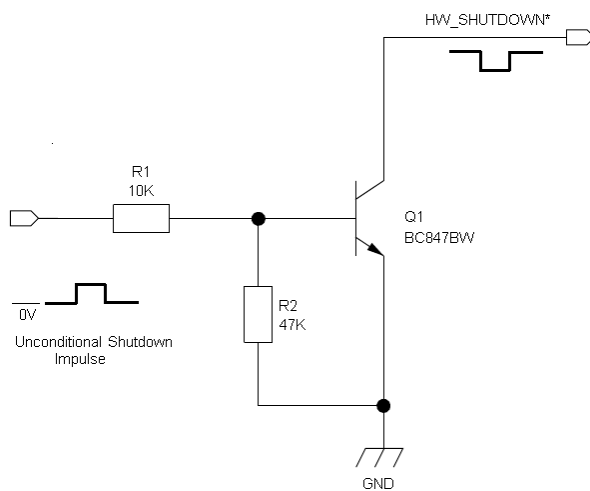
The hardware unconditional Shutdown must not be used during normal operation of the device since it does not detach the device from the network. It shall be kept as an emergency exit procedure.

A typical circuit is the following:



For example:

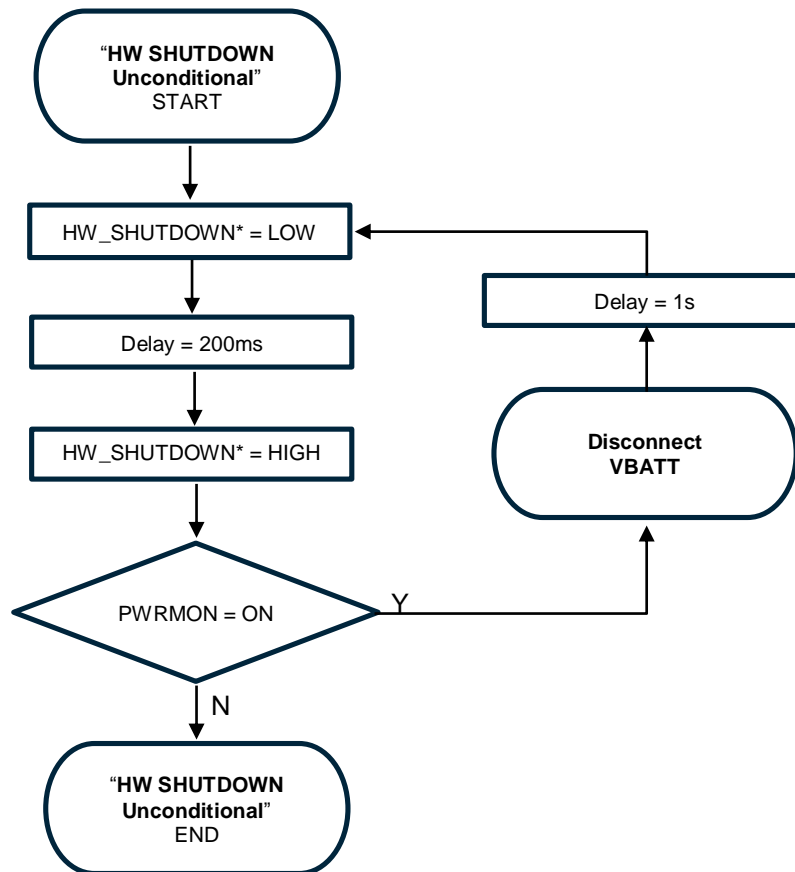
Let us assume you need to drive the HW\_SHUTDOWN\* pad with a totem pole output of a +3/5 V microcontroller (uP\_OUT2):



**NOTE:**

In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the UE910 when the module is powered off or during an ON/OFF transition.

In the following flow chart is detailed the proper restart procedure:



**NOTE:**

Do not use any pull up resistor on the HW\_SHUTDOWN\* line nor any totem pole digital output. Using pull up resistor may bring to latch up problems on the UE910 power regulator and improper functioning of the module.

To proper power on again the module please refer to the related paragraph (“Power ON”)

The unconditional hardware shutdown must always be implemented on the boards and should be used only as an emergency exit procedure.

## 5.5 Communication ports

### 5.5.1 USB 2.0 HS

The UE910 includes one integrated universal serial bus (USB 2.0 HS) transceiver.

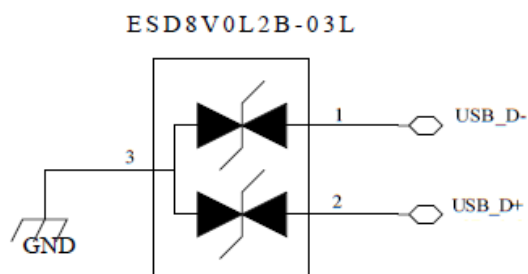
The following table is listing the available signals:

PAD	Signal	I/O	Function	Type	NOTE
<b>B15</b>	USB_D+	I/O	USB differential Data (+)	3.3V	
<b>C15</b>	USB_D-	I/O	USB differential Data (-)	3.3V	
<b>A13</b>	VUSB	AI	Power sense for the internal USB transceiver.	5V	Accepted range: 4.4V to 5.25V

The USB\_DPLUS and USB\_DMINUS signals have a clock rate of 480 MHz.

The signal traces should be routed carefully. Trace lengths, number of vias and capacitive loading should be minimized. The characteristic impedance value should be as close as possible to 90 Ohms differential.

In case there is a need to add an ESD protection, the suggested connection is the following:



**NOTE:**

VUSB pin should be disconnected before activating the Power Saving Mode.

## 5.5.2 USB HSIC

The UE910 Module is provided by one USB HSIC interface.

The USB HSIC (High Speed Inter Processor) Interface allows supporting the inter-processor communication between an application processor (AP) – the host, and the modem processor (CP) – the UE910.

The following table is listing the available signals:

PAD	Signal	I/O	Function	Type	NOTE
A12	HSIC_USB_DATA	I/O	USB HSIC data signal	CMOS 1.2V	
A11	HSIC_USB_STRB	I/O	USB HSIC strobe signal	CMOS 1.2V	
H15	HSIC_SLAVE_WAKEUP	I	Slave Wake Up	CMOS 1.8V	Shared with SPI_MRDI
F15	HSIC_HOST_WAKEUP	O	Host Wake Up	CMOS 1.8V	Shared with SPI_CLK
K15	HSIC_SUSPEND_REQUEST	O	Slave Suspend Request	CMOS 1.8V	Shared with GPIO08
J15	HSIC_HOST_ACTIVE	I	Active Host Indication	CMOS 1.8V	Shared with SPI_SRDI

For the detailed use of USB HSIC port please refer to the related Application Note.



### NOTE:

Due to the shared functions, when the USB\_HSIC port is used, it is not possible to use the SPI and GPIO\_08.

The USB\_HSIC is not active by default but it has to be enabled using the AT#PORTCFG command (refer to the AT user guide for the detailed syntax description).



### 5.5.3 SPI

The UE910 Module is provided by one SPI interface.

The SPI interface defines two handshake lines for flow control and mutual wake-up of the modem and the Application Processor: SRDY (slave ready) and MRDY (master ready).

The AP has the master role, that is, it supplies the clock.

The following table is listing the available signals:

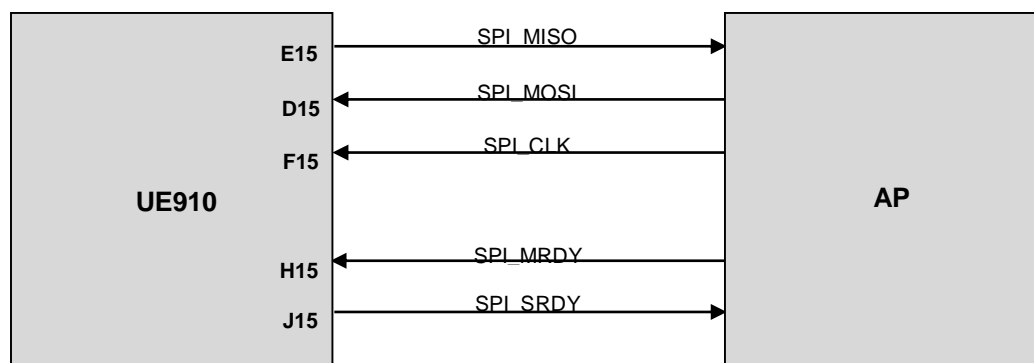
PAD	Signal	I/O	Function	Type	NOTE
D15	SPI_MOSI	I	SPI MOSI	CMOS 1.8V	Shared with TX_AUX
E15	SPI_MISO	O	SPI MISO	CMOS 1.8V	Shared with RX_AUX
F15	SPI_CLK	I	SPI Clock	CMOS 1.8V	
H15	SPI_MRDY	I	SPI_MRDY	CMOS 1.8V	
J15	SPI_SRDY	O	SPI_SRDY	CMOS 1.8V	



**NOTE:**

Due to the shared functions, when the SPI port is used, it is not possible to use the AUX\_UART port.

#### 5.5.3.1 SPI Connections



## 5.5.4 Serial Ports

The UE910 module is provided with by 2 Asynchronous serial ports:

- MODEM SERIAL PORT 1 (Main)
- MODEM SERIAL PORT 2 (Auxiliary)

Several configurations can be designed for the serial port on the OEM hardware, but the most common are:

- RS232 PC com port
- microcontroller UART @ 1.8V (Universal Asynchronous Receive Transmit)
- microcontroller UART @ 5V or other voltages different from 1.8V

Depending from the type of serial port on the OEM hardware a level translator circuit may be needed to make the system work.

On the UE910 the ports are CMOS 1.8.

### 5.5.4.1 MODEM SERIAL PORT 1 (USIF0)

The serial port 1 on the UE910 is a +1.8V UART with all the 7 RS232 signals. It differs from the PC-RS232 in the signal polarity (RS232 is reversed) and levels.

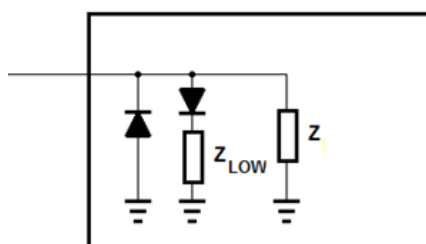
The following table is listing the available signals:

RS232 Pin	Signal	Pad	Name	Usage
1	C109/DCD	<b>N14</b>	Data Carrier Detect	Output from the UE910 that indicates the carrier presence
2	C104/RXD	<b>M15</b>	Transmit line *see Note	Output transmit line of UE910 UART
3	C103/TXD	<b>N15</b>	Receive line *see Note	Input receive of the UE910 UART
4	C108/DTR	<b>M14</b>	Data Terminal Ready	Input to the UE910 that controls the DTE READY condition
5	GND	<b>M12, B13, P13, E14 ...</b>	Ground	Ground
6	C107/DSR	<b>P14</b>	Data Set Ready	Output from the UE910 that indicates the module is ready
7	C106/CTS	<b>P15</b>	Clear to Send	Output from the UE910 that controls the Hardware flow control
8	C105/RTS	<b>L14</b>	Request to Send	Input to the UE910 that controls the Hardware flow control
9	C125/RING	<b>R14</b>	Ring Indicator	Output from the UE910 that indicates the incoming call condition

The following table shows the typical input value of internal pull-up resistors for RTS, DTR and TXD input lines and in all module states:

STATE	RTS DTR TXD	
	Pull up tied to	
ON	5K to 12K	1V8
OFF	Schottky diode	
RESET	Schottky diode	
POWER SAVING	5K to 12K	1V8

The input line ON\_OFF and HW\_SHDN state can be treated as in picture below



**NOTE:**

According to V.24, some signal names are referred to the application side, therefore on the UE910 side these signal are on the opposite direction:  
 TXD on the application side will be connected to the receive line (here named C103/TXD)  
 RXD on the application side will be connected to the transmit line (here named C104/RXD)

For a minimum implementation, only the TXD, RXD lines can be connected, the other lines can be left open provided a software flow control is implemented.

In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the UE910 when the module is powered off or during an ON/OFF transition.

### 5.5.4.2 MODEM SERIAL PORT 2 (USIF1)

The secondary serial port on the UE910 is a CMOS1.8V with only the RX and TX signals.

The signals of the UE910 serial port are:

PAD	Signal	I/O	Function	Type	NOTE
D15	TX_AUX	O	Auxiliary UART (TX Data to DTE)	CMOS 1.8V	Shared with SPI_MOSI
E15	RX_AUX	I	Auxiliary UART (RX Data from DTE)	CMOS 1.8V	Shared with SPI_MISO



**NOTE:**

Due to the shared pins, when the Modem Serial port is used, it is not possible to use the SPI functions.

In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the UE910 when the module is powered off or during an ON/OFF transition.

### 5.5.4.3 RS232 LEVEL TRANSLATION

In order to interface the UE910 with a PC com port or a RS232 (EIA/TIA-232) application a level translator is required. This level translator must:

- invert the electrical signal in both directions;
- Change the level from 0/1.8V to +15/-15V.

Actually, the RS232 UART 16450, 16550, 16650 & 16750 chipsets accept signals with lower levels on the RS232 side (EIA/TIA-562), allowing a lower voltage-multiplying ratio on the level translator. Note that the negative signal voltage must be less than 0V and hence some sort of level translation is always required.

The simplest way to translate the levels and invert the signal is by using a single chip level translator. There are a multitude of them, differing in the number of drivers and receivers and in the levels (be sure to get a true RS232 level translator not a RS485 or other standards).

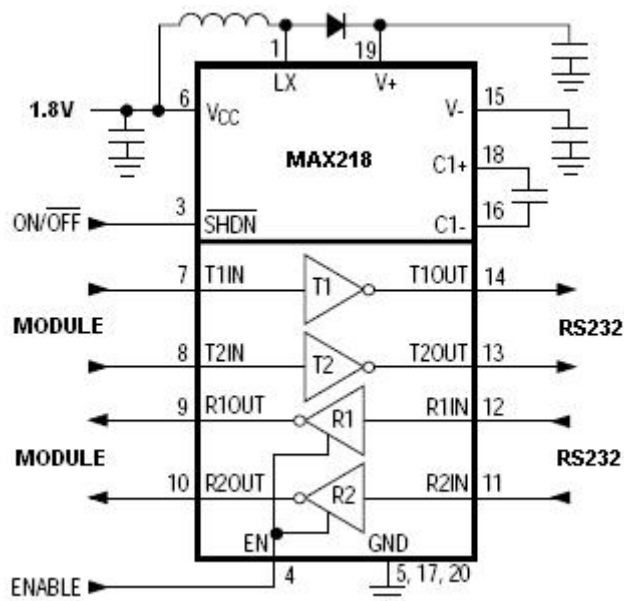
By convention the driver is the level translator from the 0-1.8V UART to the RS232 level. The receiver is the translator from the RS232 level to 0-1.8V UART.

In order to translate the whole set of control lines of the UART you will need:

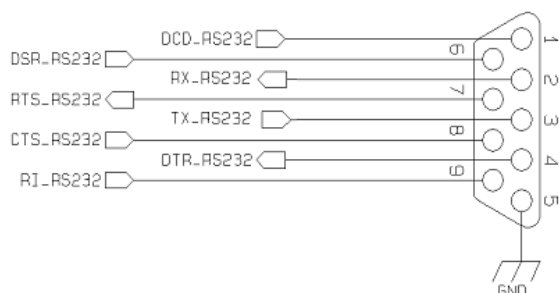
- 5 drivers
- 3 receivers

An example of RS232 level adaptation circuitry could be done using a MAXIM transceiver (MAX218)

In this case the chipset is capable to translate directly from 1.8V to the RS232 levels (Example done on 4 signals only).



The RS232 serial port lines are usually connected to a DB9 connector with the following layout:



## 5.6 General Purpose I/O

The UE910 module is provided by a set of Configurable Digital Input / Output pins (CMOS 1.8V)

Input pads can only be read; they report the digital value (high or low) present on the pad at the read time.

Output pads can only be written or queried and set the value of the pad output.

An alternate function pad is internally controlled by the UE910 firmware and acts depending on the function implemented.

The following table shows the available GPIO on the UE910:

PAD	Signal	I/O	Drive Strength	Default State	NOTE
<b>C8</b>	GPIO_01	I/O	1 mA	INPUT	Alternate function STAT LED
<b>C9</b>	GPIO_02	I/O	1 mA	INPUT	
<b>C10</b>	GPIO_03	I/O	1 mA	INPUT	
<b>C11</b>	GPIO_04	I/O	1 mA	INPUT	
<b>B14</b>	GPIO_05	I/O	1 mA	INPUT	
<b>C12</b>	GPIO_06	I/O	1 mA	INPUT	
<b>C13</b>	GPIO_07	I/O	1 mA	INPUT	
<b>K15</b>	GPIO_08	I/O	1 mA	INPUT	
<b>L15</b>	GPIO_09	I/O	1 mA	INPUT	
<b>G15</b>	GPIO_10	I/O	1 mA	INPUT	

### 5.6.1 Using a GPIO as INPUT

The GPIO pads, when used as inputs, can be connected to a digital output of another device and report its status, provided this device has interface levels compatible with the 1.8V CMOS levels of the GPIO.

If the digital output of the device to be connected with the GPIO input pad has interface levels different from the 1.8V CMOS, then it can be buffered with an open collector transistor with a 47K pull up to 1.8V.



#### NOTE:

In order to avoid a back powering effect it is recommended to avoid having any HIGH logic level signal applied to the digital pins of the UE910 when the module is powered off or during an ON/OFF transition.

---

### 5.6.2 Using a GPIO as OUTPUT

The GPIO pads, when used as outputs, can drive 1.8V CMOS digital devices or compatible hardware. When set as outputs, the pads have a push-pull output and therefore the pull-up resistor may be omitted.

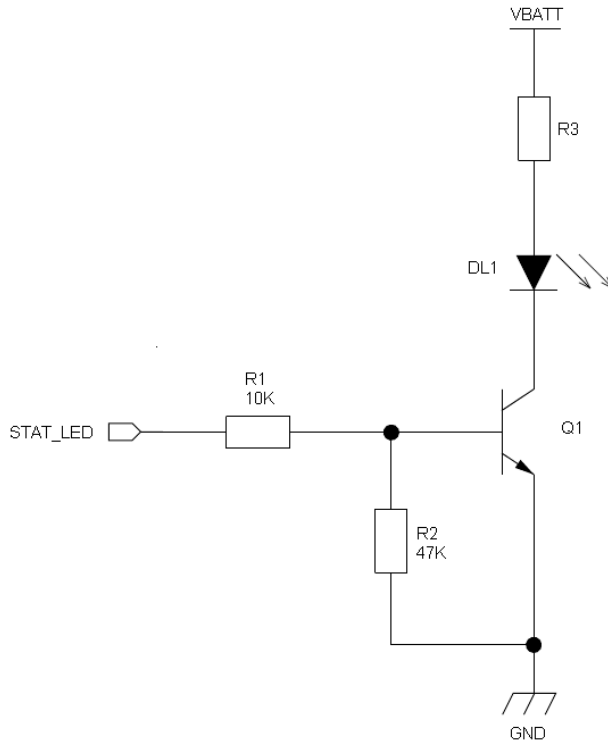
### 5.6.3 Indication of network service availability

The STAT\_LED pin status shows information on the network service availability and Call status. The function is available as alternate function of GPIO\_01 (to be enabled using the AT#GPIO=1,0,2 command).

In the UE910 modules, the STAT\_LED needs an external transistor to drive an external LED. Therefore, the status indicated in the following table is reversed with respect to the pin status.

Device Status	Led Status
Device off	Permanently off
Not Registered	Permanently on
Registered in idle	Blinking 1sec on + 2 sec off
Registered in idle + power saving	It depends on the event that triggers the wakeup (In sync with network paging)
Voice Call Active	Permanently on
Dial-Up	Blinking 1 sec on + 2 sec off

A schematic example could be:





## 5.7 External SIM Holder

Please refer to the related User Guide (SIM Holder Design Guides, 80000NT10001a).

## 5.8 ADC Converter

The UE910 is provided by one AD converter. It is able to read a voltage level in the range of 0÷1.2 volts applied on the ADC pin input, store and convert it into 10 bit word.

The input line is named as **ADC\_IN1** and it is available on Pad **B1**

The following table is showing the ADC characteristics:

Item	Min	Typical	Max	Unit
Input Voltage range	0	-	1.2	Volt
AD conversion	-	-	10	bits
Input Resistance	1	-	-	Mohm
Input Capacitance	-	1	-	pF

The ADC could be controlled using an AT command.

The command is **AT#ADC=1,2**

The read value is expressed in mV

Refer to SW User Guide or AT Commands Reference Guide for the full description of this function.

## 6 RF SECTION

### 6.1 Bands Variants

The following table is listing the supported Bands:

Product	Supported 3G bands
UE910-N3G	FDD B2, B5

### 6.2 TX Output Power

Band	Power Class
FDD B2, B5	Class 3 (0.25W)

### 6.3 RX Sensitivity

Band	Sensitivity
FDD B2, B5	-111dBm

## 6.4 Antenna Requirements

The antenna connection and board layout design are the most important aspect in the full product design as they strongly affect the product overall performances, hence read carefully and follow the requirements and the guidelines for a proper design.

The antenna and antenna transmission line on PCB for a Telit UE910 device shall fulfil the following requirements:

Item	Value
Frequency range	Depending by frequency band(s) provided by the network operator, the customer shall use the most suitable antenna for that/those band(s)
Bandwidth	70 MHz in WCDMA Band V 140 MHz in WCDMA Band II
Impedance	50 ohm
Input power	> 24dBm Average power
VSWR absolute max	≤ 10:1 (limit to avoid permanent damage)
VSWR recommended	≤ 2:1 (limit to fulfill all regulatory requirements)

### 6.4.1 PCB design guidelines

When using the UE910, since there's no antenna connector on the module, the antenna must be connected to the UE910 antenna pad (K1) by means of a transmission line implemented on the PCB. In the case the antenna is not directly connected at the antenna pad of the UE910, then a PCB line is needed in order to connect with it or with its connector.

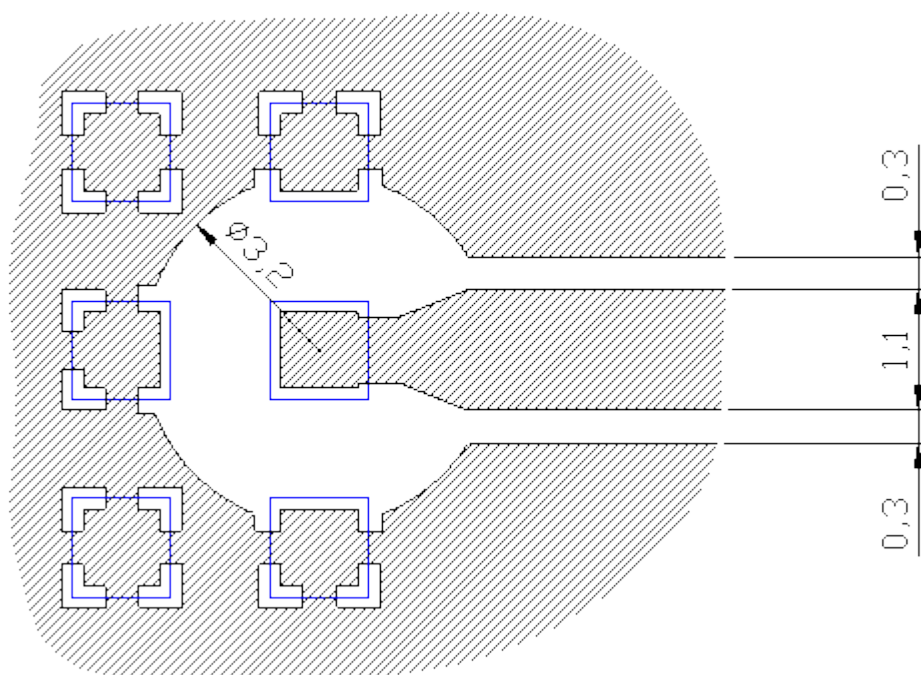
This transmission line shall fulfil the following requirements:

Item	Value
Characteristic Impedance	50 ohm
Max Attenuation	0,3 dB
Coupling	Coupling with other signals shall be avoided
Ground Plane	Cold End (Ground Plane) of antenna shall be equipotential to the UE910 ground pins

The transmission line should be designed according to the following guidelines:

- Ensure that the antenna line impedance is 50 ohm;
- Keep the antenna line on the PCB as short as possible, since the antenna line loss shall be less than 0,3 dB;
- Antenna line must have uniform characteristics, constant cross section; avoid meanders and abrupt curves;
- Keep, if possible, one layer of the PCB used only for the Ground plane;
- Surround (on the sides, over and under) the antenna line on PCB with Ground, avoid having other signal tracks facing directly the antenna line track;
- The ground around the antenna line on PCB has to be strictly connected to the Ground Plane by placing vias every 2mm at least;
- Place EM noisy devices as far as possible from UE910 antenna line;
- Keep the antenna line far away from the UE910 power supply lines;
- If you have EM noisy devices around the PCB hosting the UE910, such as fast switching ICs, take care of the shielding of the antenna line by burying it inside the layers of PCB and surround it with Ground planes, or shield it with a metal frame cover.
- If you don't have EM noisy devices around the PCB of UE910, by using a micro strip on the superficial copper layer for the antenna line, the line attenuation will be lower than a buried one;

The following image is showing the suggested layout for the Antenna pad connection:



## 6.4.2 PCB Guidelines in case of FCC Certification

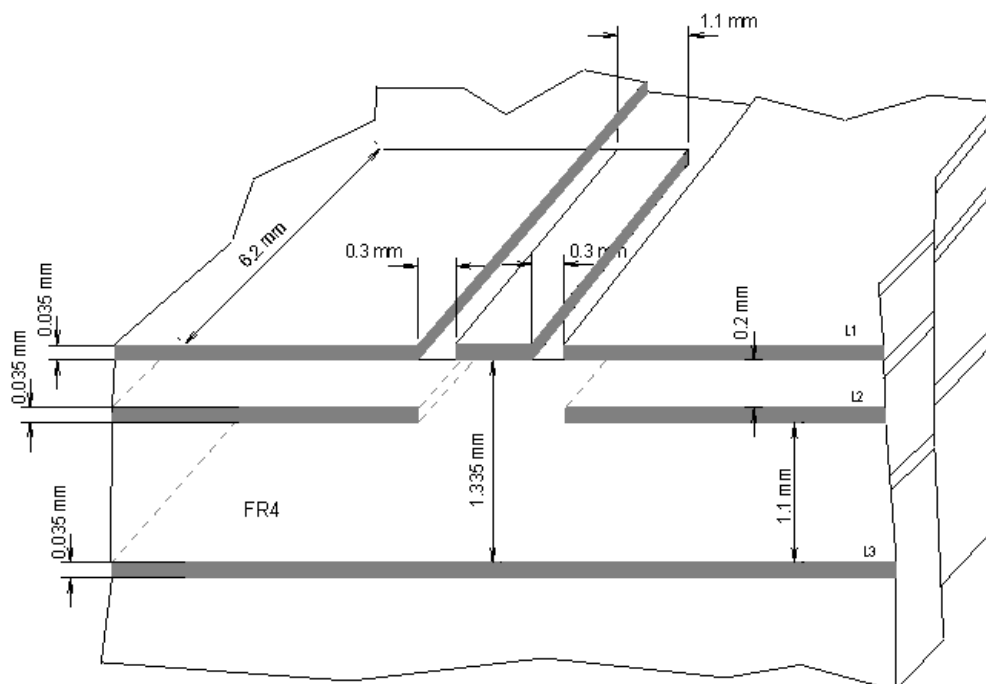
In the case FCC certification is required for an application using UE910-N3G, according to FCC KDB 996369 for modular approval requirements, the transmission line has to be similar to that implemented on UE910 interface board and described in the following chapter.

### 6.4.2.1 *Transmission line design*

During the design of the UE910 interface board, the placement of components has been chosen properly, in order to keep the line length as short as possible, thus leading to lowest power losses possible. A Grounded Coplanar Waveguide (G-CPW) line has been chosen, since this kind of transmission line ensures good impedance control and can be implemented in an outer PCB layer as needed in this case. A SMA female connector has been used to feed the line.

The interface board is realized on a FR4, 4-layers PCB. Substrate material is characterized by relative permittivity  $\epsilon_r = 4.6 \pm 0.4 @ 1 \text{ GHz}$ ,  $\text{TanD} = 0.019 \div 0.026 @ 1 \text{ GHz}$ .

A characteristic impedance of nearly  $50 \Omega$  is achieved using trace width = 1.1 mm, clearance from coplanar ground plane = 0.3 mm each side. The line uses reference ground plane on layer 3, while copper is removed from layer 2 underneath the line. Height of trace above ground plane is 1.335 mm. Calculated characteristic impedance is  $51.6 \Omega$ , estimated line loss is less than 0.1 dB. The line geometry is shown below:

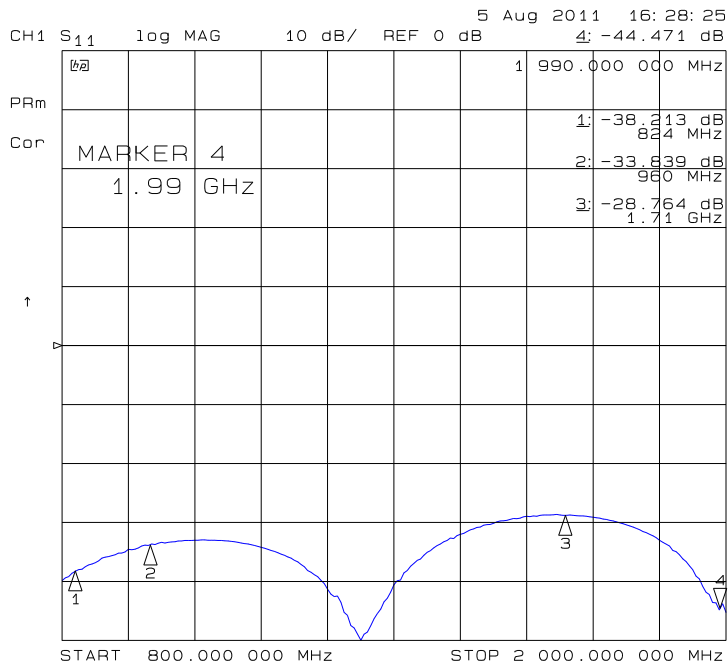


### 6.4.2.2 Transmission Line Measurements

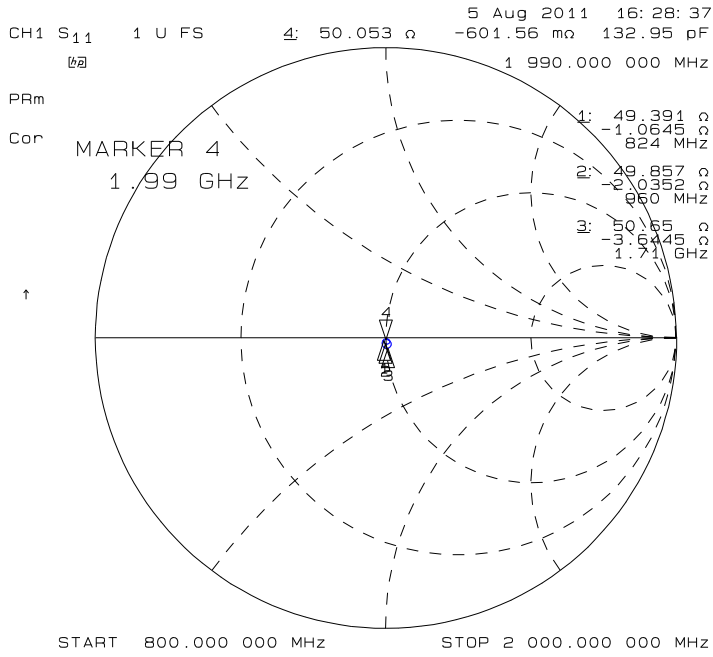
An HP8753E VNA (Full-2-port calibration) has been used in this measurement session.

A calibrated coaxial cable has been soldered at the pad corresponding to RF output; a SMA connector has been soldered to the board in order to characterize the losses of the transmission line including the connector itself. During Return Loss / impedance measurements, the transmission line has been terminated to 50  $\Omega$  load.

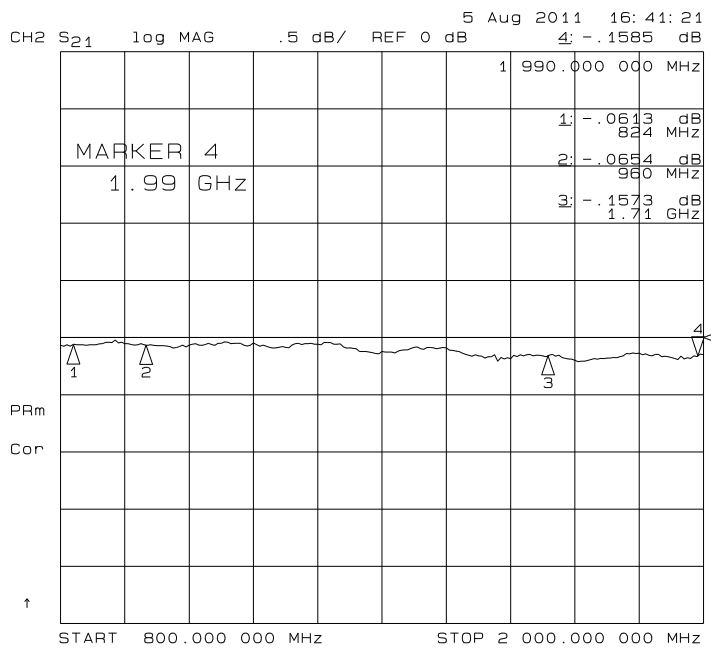
Return Loss plot of line under test is shown below:



Line input impedance (in Smith Chart format, once the line has been terminated to 50  $\Omega$  load) is shown in the following figure:



Insertion Loss of G-CPW line plus SMA connector is shown below:



### 6.4.2.3 *Antenna Installation Guidelines*

Install the antenna in a place covered by the WCDMA signal.

If the device antenna is located farther than 20cm from the human body and there are no co-located transmitter then the Telit FCC/IC approvals can be re-used by the end product.

If the device antenna is located closer than 20cm from the human body or there are co-located transmitter then the additional FCC/IC testing may be required for the end product (Telit FCC/IC approvals cannot be reused).

Antenna shall not be installed inside metal cases.

Antenna shall be installed also according to antenna manufacturer instructions.



# 7 AUDIO SECTION

## 7.1 Overview

The UE910 is provided by two main Audio interfaces:

- Analog Audio Path
- Digital Audio Path



**NOTE:**

The two Paths could not be used in parallel; If the Analog Voice lines are selected, the DVI interface is disabled and Vice versa.

## 7.2 Analog Voice Interface

The Base Band Chip of the UE910 provides one differential input for audio to be transmitted (Uplink) and a balanced BTL output for audio to be received (downlink).

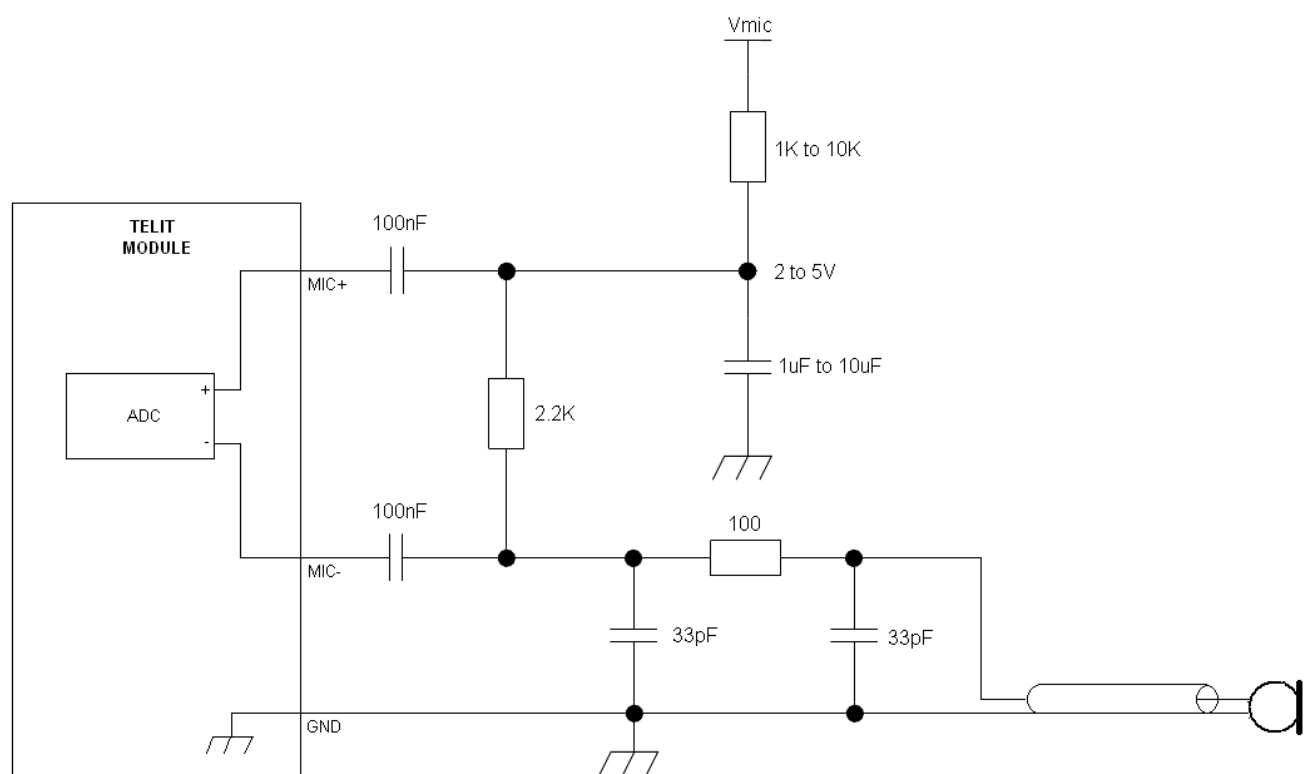
The Signals are available on the following Pads:

PAD	Signal	I/O	Function
B2	EAR+	O	Analog Voice Interface (EAR+)
B3	EAR-	O	Analog Voice Interface (EAR-)
B4	MIC+	I	Analog Voice Interface (MIC+)
B5	MIC-	I	Analog Voice Interface (MIC-)

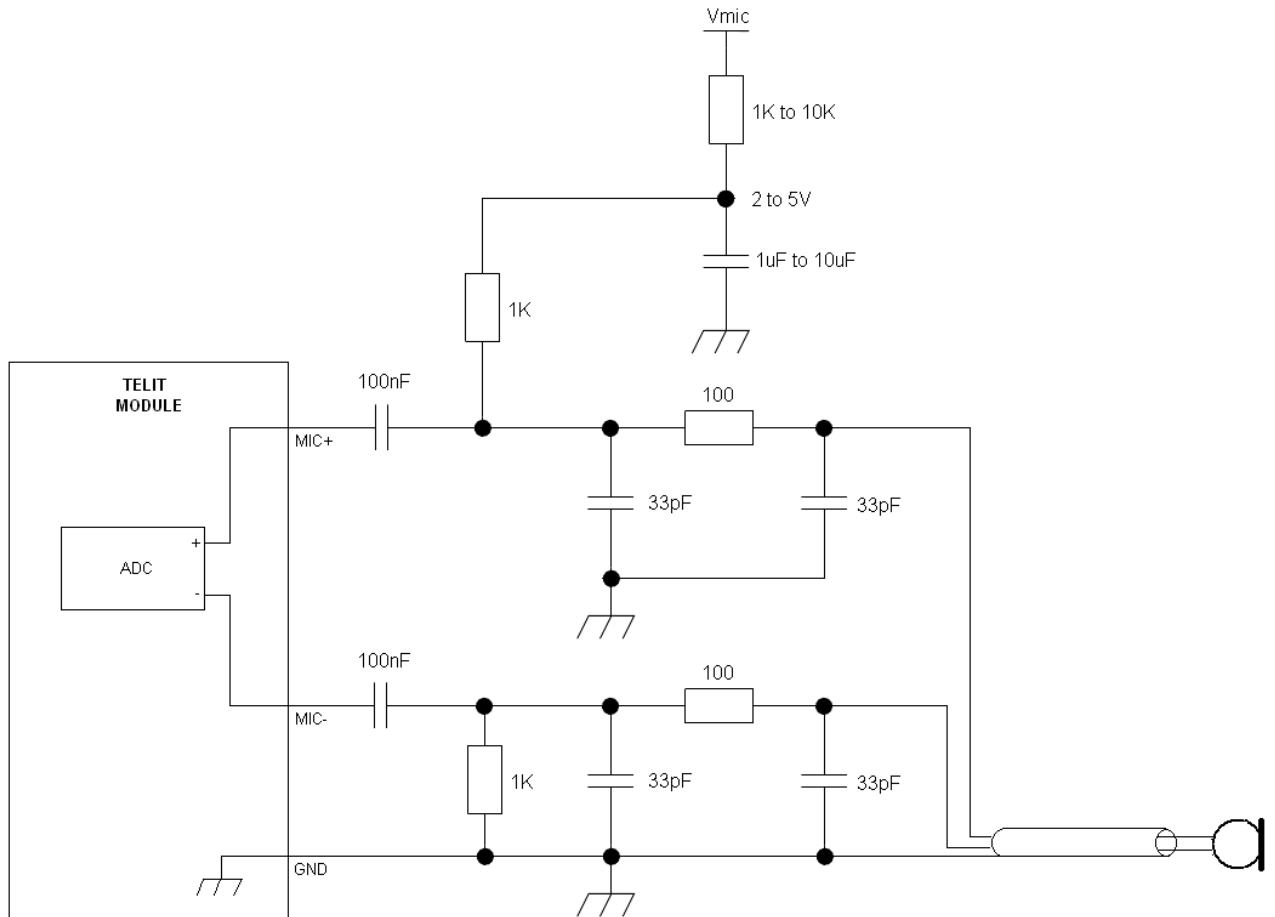
## 7.2.1 MIC connection

The bias for the microphone has to be as clean as possible; the first connection (single ended) is preferable since the  $V_{mic}$  noise and ground noise are fed into the input as common mode and then rejected. This sounds strange; usually the connection to use in order to reject the common mode is the balanced one. In this situation we have to recall that the microphone is a sound to current transducer, so the resistor is the current to tension transducer, so finally the resistor feeds the input in balanced way even if the configuration, from a microphone point of view, seems to be un-balanced.

The following images show some connection examples:



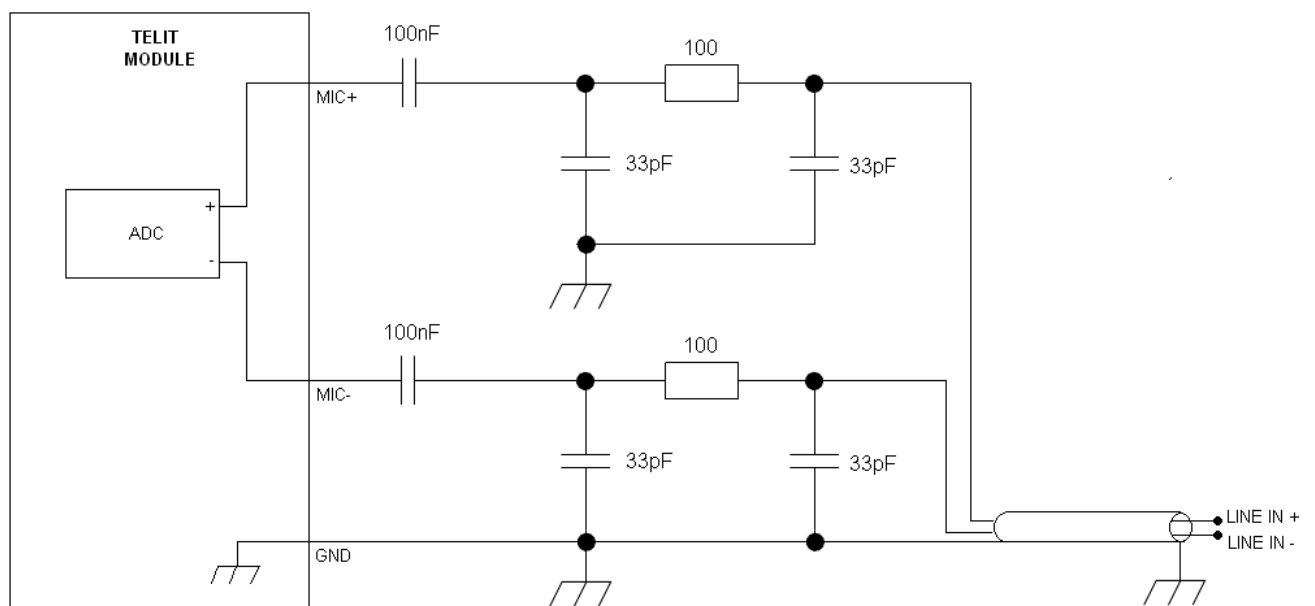
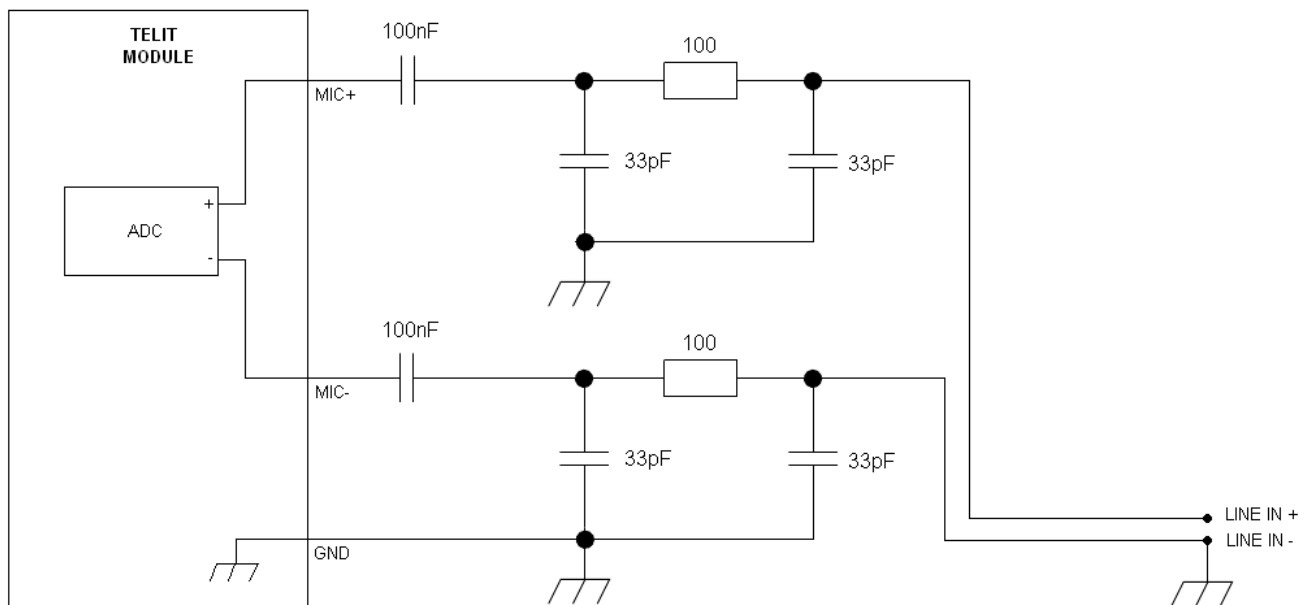
If a "balanced way" is anyway desired, much more care has to be taken to Vmic noise and ground noise; also the 33pF-100Ohm-33pF RF-filter has to be doubled (one each wire).



**NOTE:**

Since the J-FET transistor inside the microphone acts as RF-detector-amplifier, ask vendor for a microphone with anti-EMI capacitor (usually a 33pF or a 10pF capacitor placed across the output terminals inside the case).

## 7.2.2 LINE IN Connection



If the audio source is not a mike but a different device, the following connections can be done.

Place 100nF capacitor in series with both inputs, so the DC current is blocked.

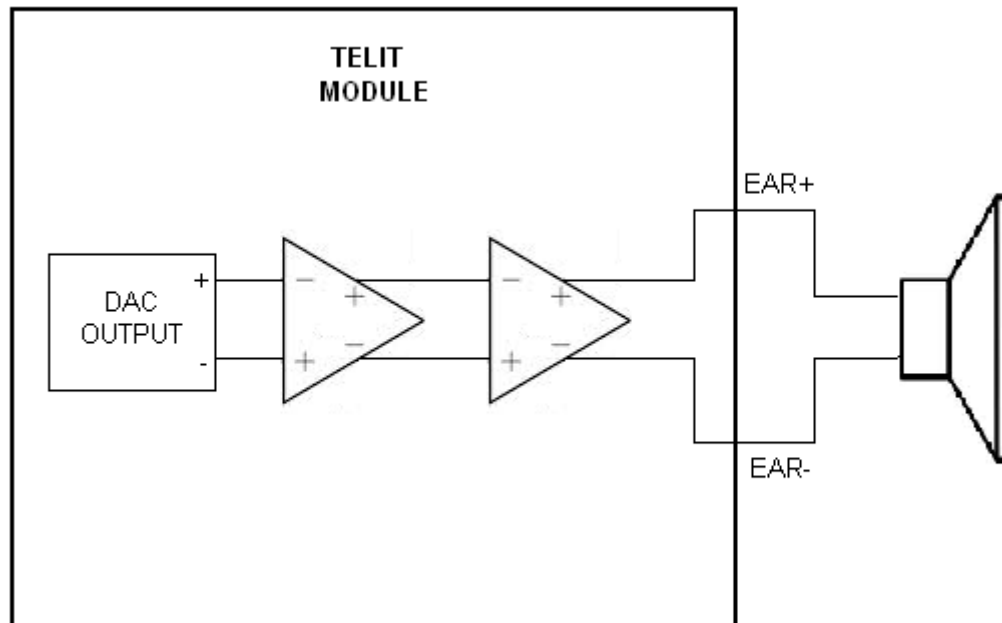
Place the 33pF-100Ohm-33pF RF-filter, in order to prevent some EMI field to get into the high impedance high gain MIC inputs.

Since the input is differential, the common mode voltage noise between the two (different) ground is rejected, provided that both MIC+ & MIC- are connected directly onto the source.

### 7.2.3 EAR Connection

The audio output of the UE910 is balanced, this is helpful to double the level and to reject common mode (click and pop are common mode and therefore rejected).

These outputs can drive directly a small loudspeaker with electrical impedance not lower than 16 Ohm.



**NOTE:**

In order to get the maximum audio level at a given output voltage level (dBspl/Vrms), the following breaking through procedure can be used. Have the loudspeaker as close as you can to the listener (this simplify also the echo cancelling); choose the loudspeaker with the higher sensitivity (dBspl per W); choose loudspeakers with the impedance close to the limit, in order to feed more power inside the transducer (it increases the W/Vrms ratio). If this were not enough, an external amplifier should be used.

## 7.3 Digital Voice Interface

The UE910 Module is provided by one DVI digital voice interface.

The Signals are available on the following Pads:

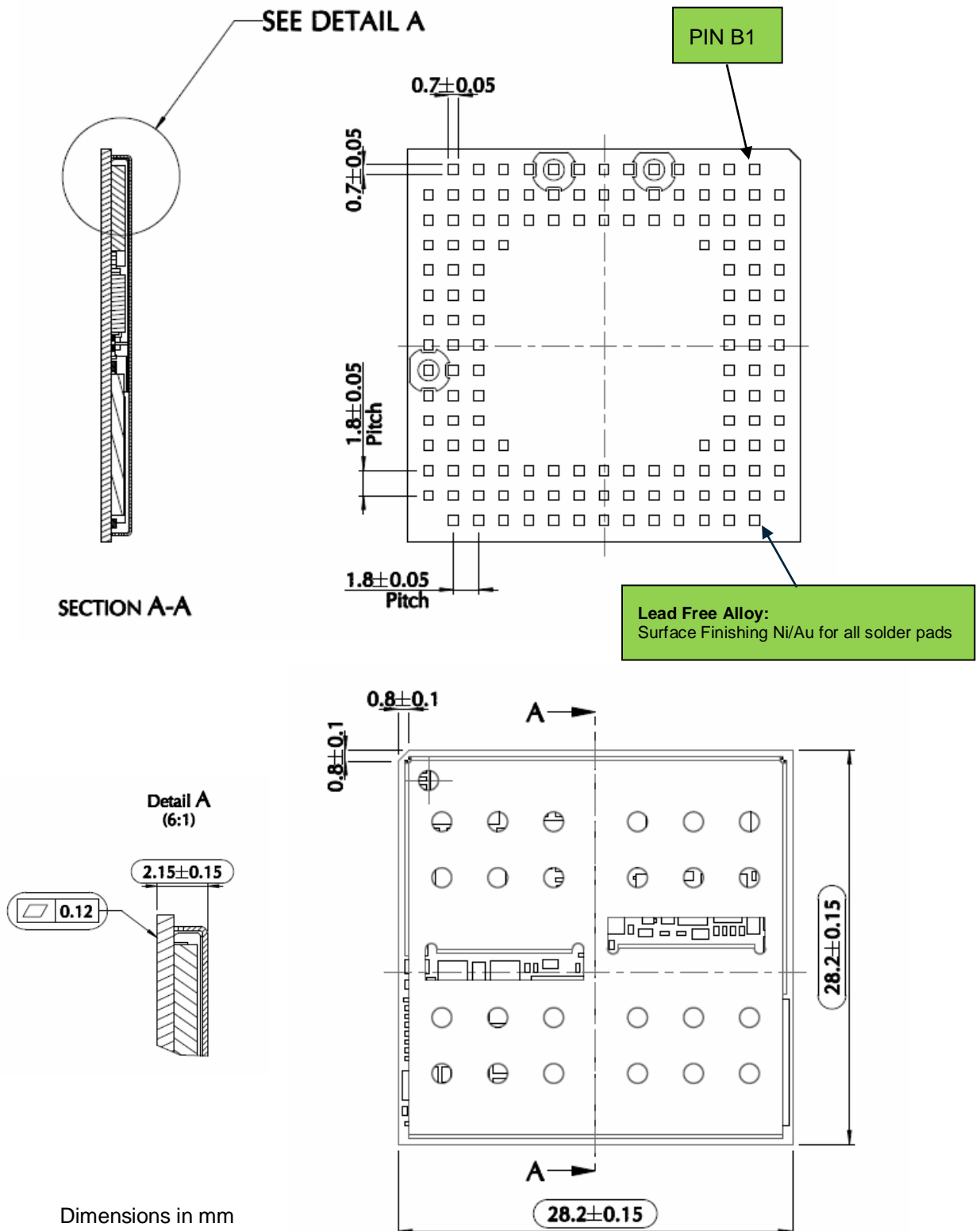
PAD	Signal	I/O	Function
<b>B9</b>	DVI_WA0	I/O	Digital Voice Interface (Word Alignment / LRCLK)
<b>B6</b>	DVI_RX	I	Digital Voice Interface (RX)
<b>B7</b>	DVI_TX	O	Digital Voice Interface (TX)
<b>B8</b>	DVI_CLK	I/O	Digital Voice Interface (BCLK)

### 7.3.1 CODEC Examples

Please refer to the Digital Audio Application note.

# 8 MECHANICAL DESIGN

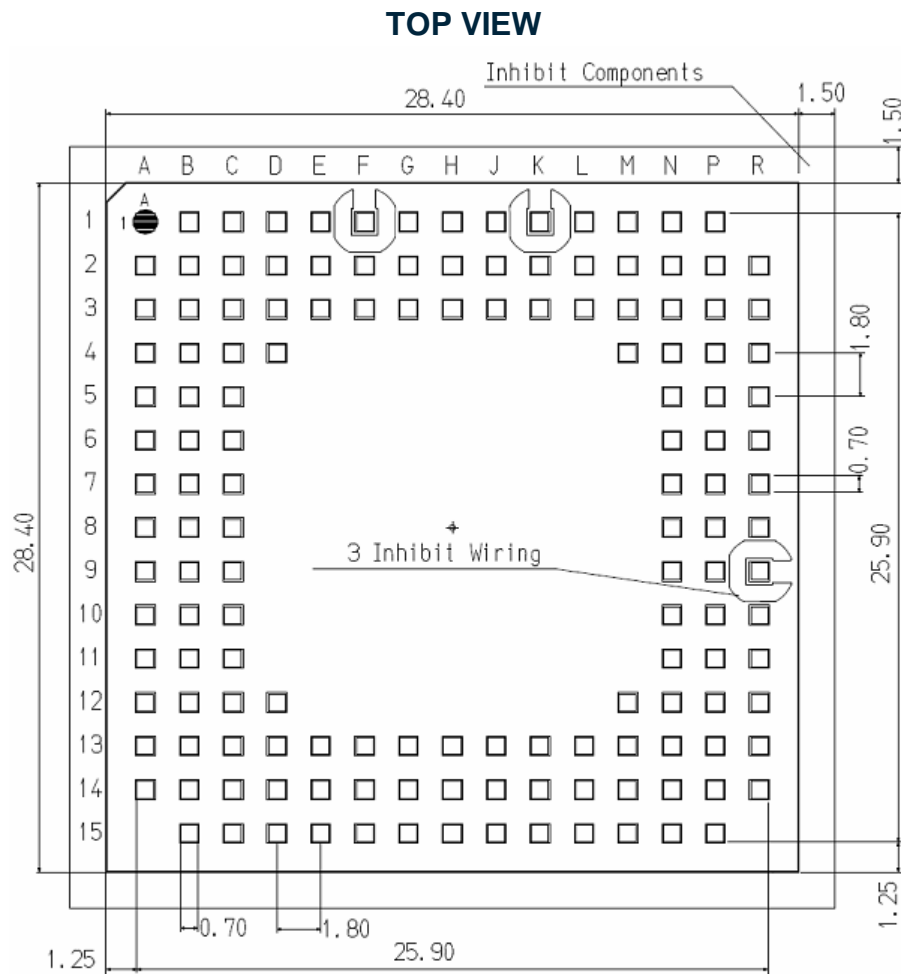
## 8.1 Drawing



# 9 APPLICATION DESIGN

The UE910 modules have been designed in order to be compliant with a standard lead-free SMT process.

## 9.1 Footprint



In order to easily rework the UE910 is suggested to consider on the application a 1.5 mm placement inhibit area around the module.

It is also suggested, as common rule for an SMT component, to avoid having a mechanical part of the application in direct contact with the module.



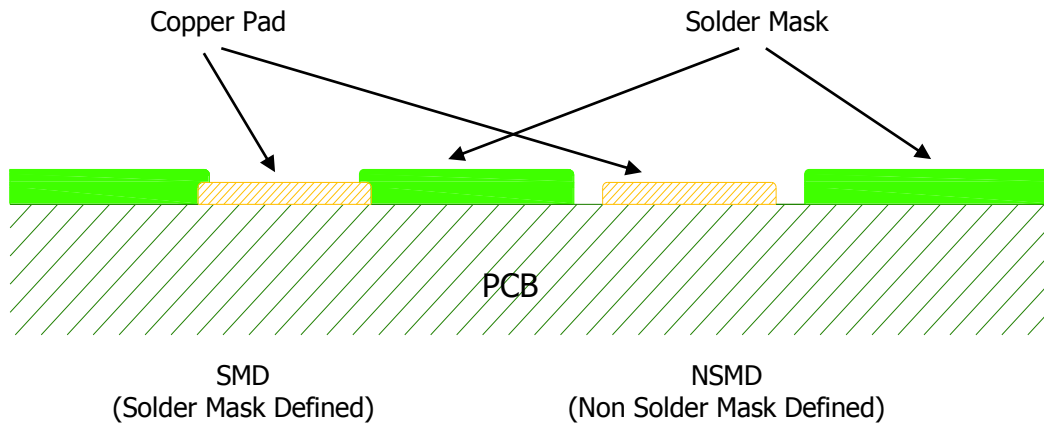
**NOTE:**

In the customer application, the region under WIRING INHIBIT (see figure above) must be clear from signal or ground paths.



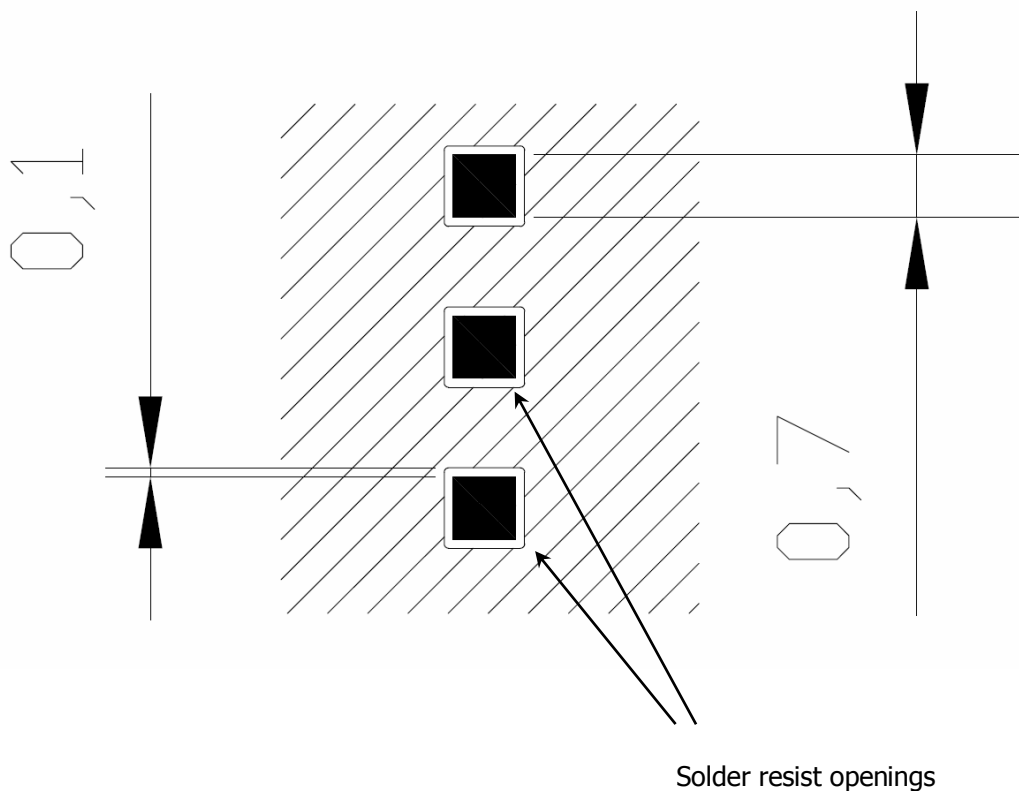
## 9.2 PCB pad design

Non solder mask defined (NSMD) type is recommended for the solder pads on the PCB.

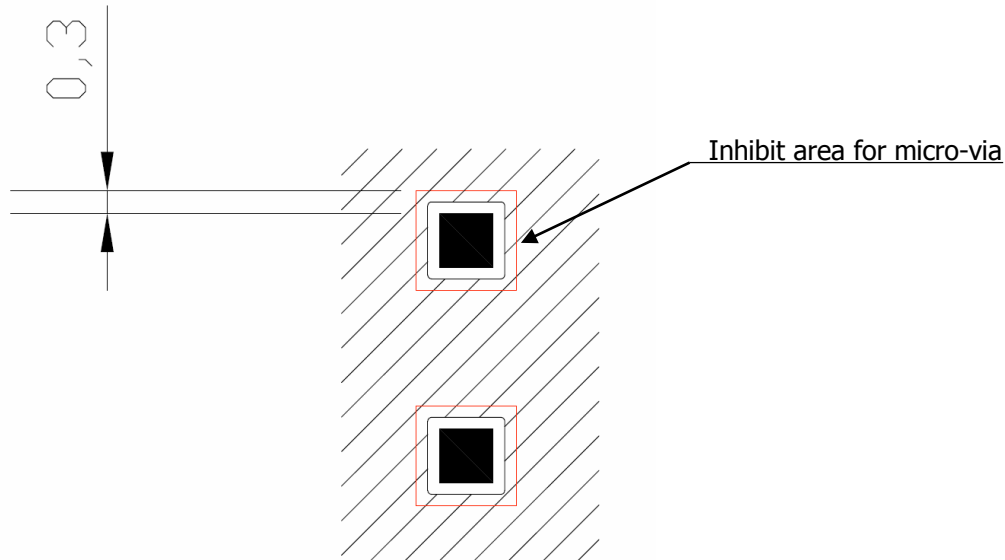


## 9.3 PCB pad dimensions

The recommendation for the PCB pads dimensions are described in the following image (dimensions in mm)



It is not recommended to place via or micro-via not covered by solder resist in an area of 0,3 mm around the pads unless it carries the same signal of the pad itself



Holes in pad are allowed only for blind holes and not for through holes.

Recommendations for PCB pad surfaces:

Finish	Layer Thickness (um)	Properties
Electro-less Ni / Immersion Au	3 –7 / 0.05 – 0.15	good solder ability protection, high shear force values

The PCB must be able to resist the higher temperatures which are occurring at the lead-free process. This issue should be discussed with the PCB-supplier. Generally, the wettability of tin-lead solder paste on the described surface plating is better compared to lead-free solder paste.

It is not necessary to panel the application’s PCB, however in that case it is suggested to use milled contours and predrilled board breakouts; scoring or v-cut solutions are not recommended.

## 9.4 Stencil

Stencil's apertures layout can be the same of the recommended footprint (1:1), we suggest a thickness of stencil foil  $\geq 120 \mu\text{m}$ .

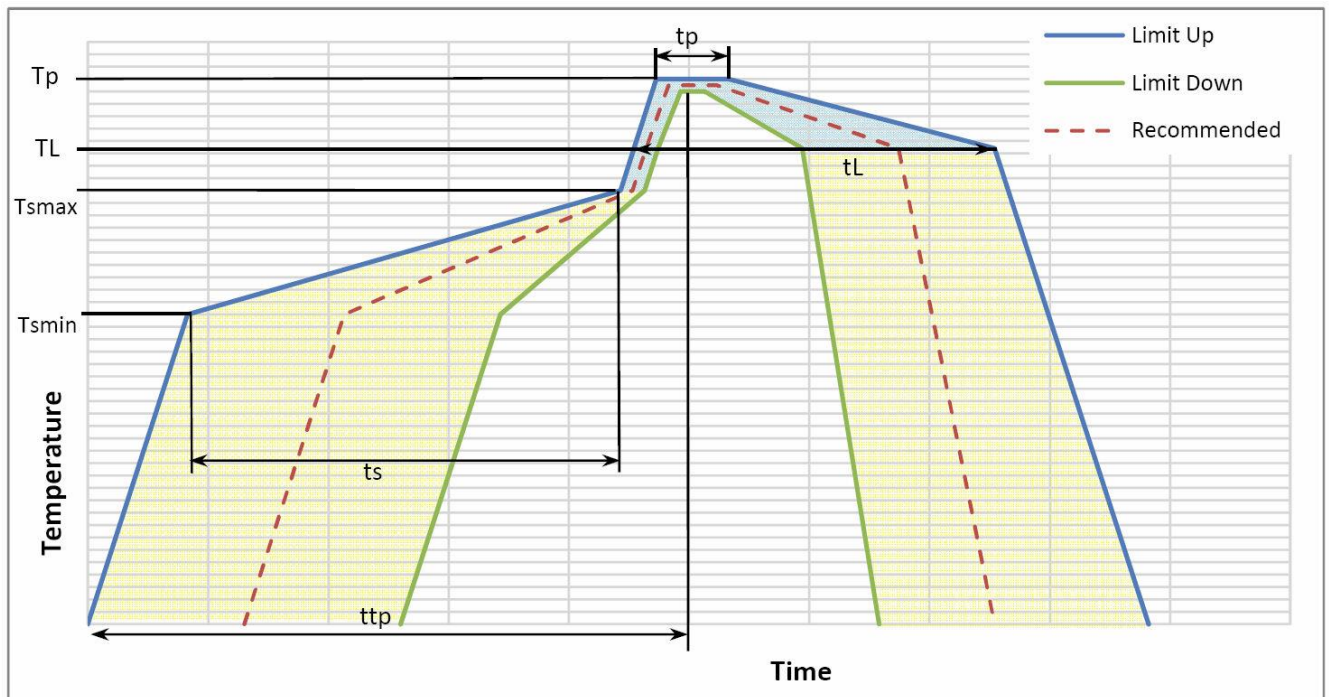
## 9.5 Solder paste

Item	Lead Free
Solder Paste	Sn/Ag/Cu

We recommend using only “no clean” solder paste in order to avoid the cleaning of the modules after assembly.

## 9.6 Solder reflow

Recommended solder reflow profile:



Profile Feature	Pb-Free Assembly
Average ramp-up rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/second max
Preheat	
– Temperature Min (T <sub>smin</sub> )	150°C
– Temperature Max (T <sub>smax</sub> )	200°C
– Time (min to max) (ts)	60-180 seconds
T <sub>smax</sub> to T <sub>L</sub>	
– Ramp-up Rate	3°C/second max
Time maintained above:	
– Temperature (T <sub>L</sub> )	217°C
– Time (t <sub>L</sub> )	60-150 seconds
Peak Temperature (T <sub>p</sub> )	245 +0/-5°C
Time within 5°C of actual Peak Temperature (t <sub>p</sub> )	10-30 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.



**NOTE:**

All temperatures refer to topside of the package, measured on the package body surface



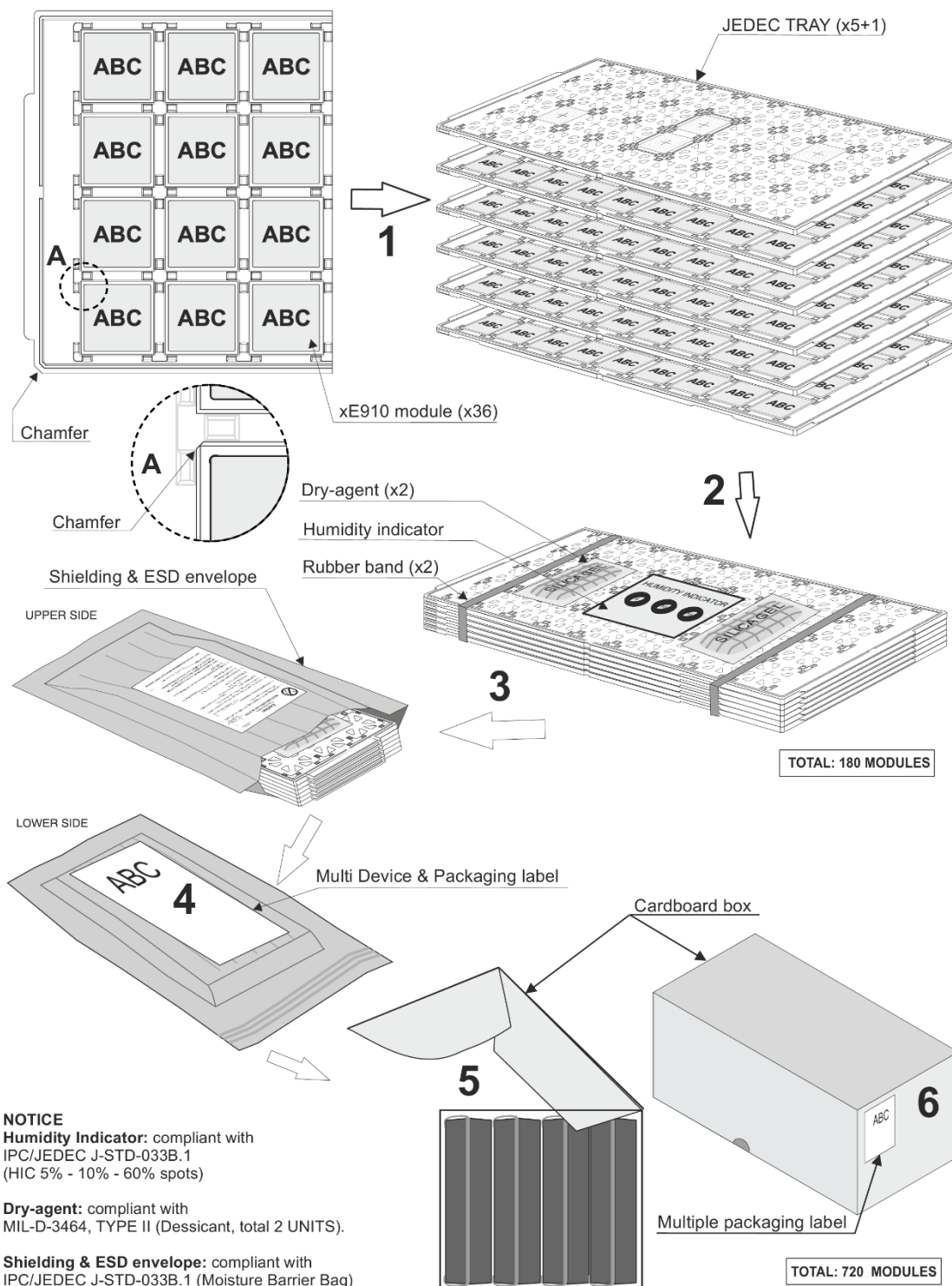
**WARNING:**

The UE910 module withstands one reflow process only.

# 10 PACKAGING

## 10.1 Tray

The UE910 modules are packaged on trays of **36** pieces each. These trays can be used in SMT processes for pick & place handling.



**NOTICE**

**Humidity Indicator:** compliant with IPC/JEDEC J-STD-033B.1 (HIC 5% - 10% - 60% spots)

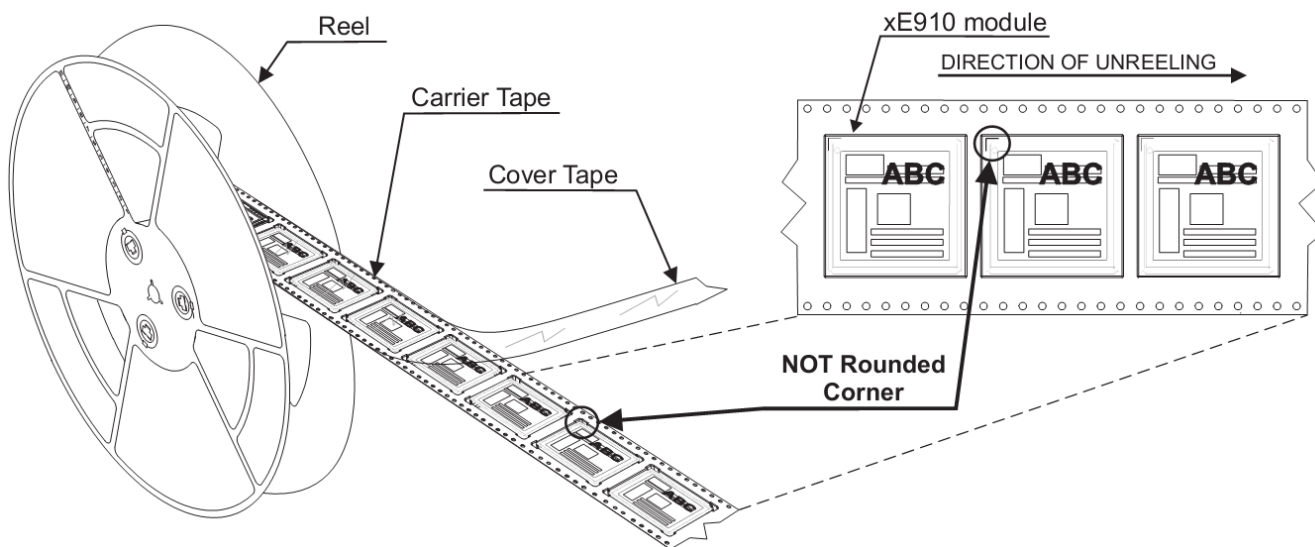
**Dry-agent:** compliant with MIL-D-3464, TYPE II (Dessicant, total 2 UNITS).

**Shielding & ESD envelope:** compliant with IPC/JEDEC J-STD-033B.1 (Moisture Barrier Bag)

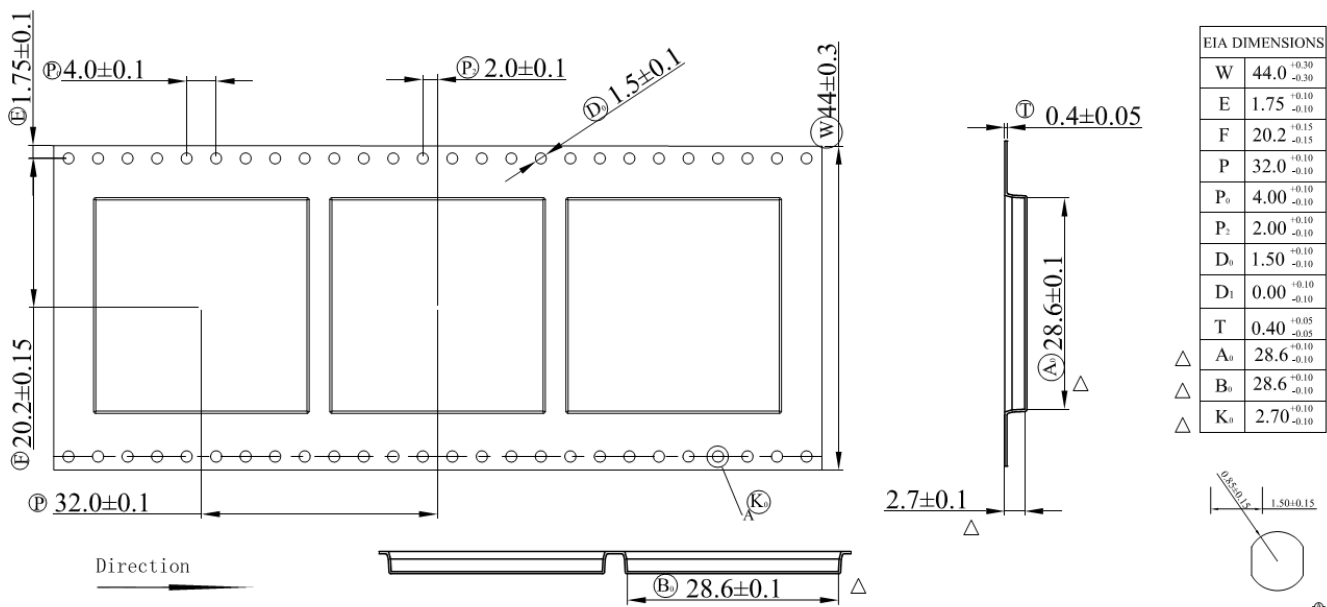
## 10.2 Reel

The UE910 can be packaged on reels of 200 pieces each.

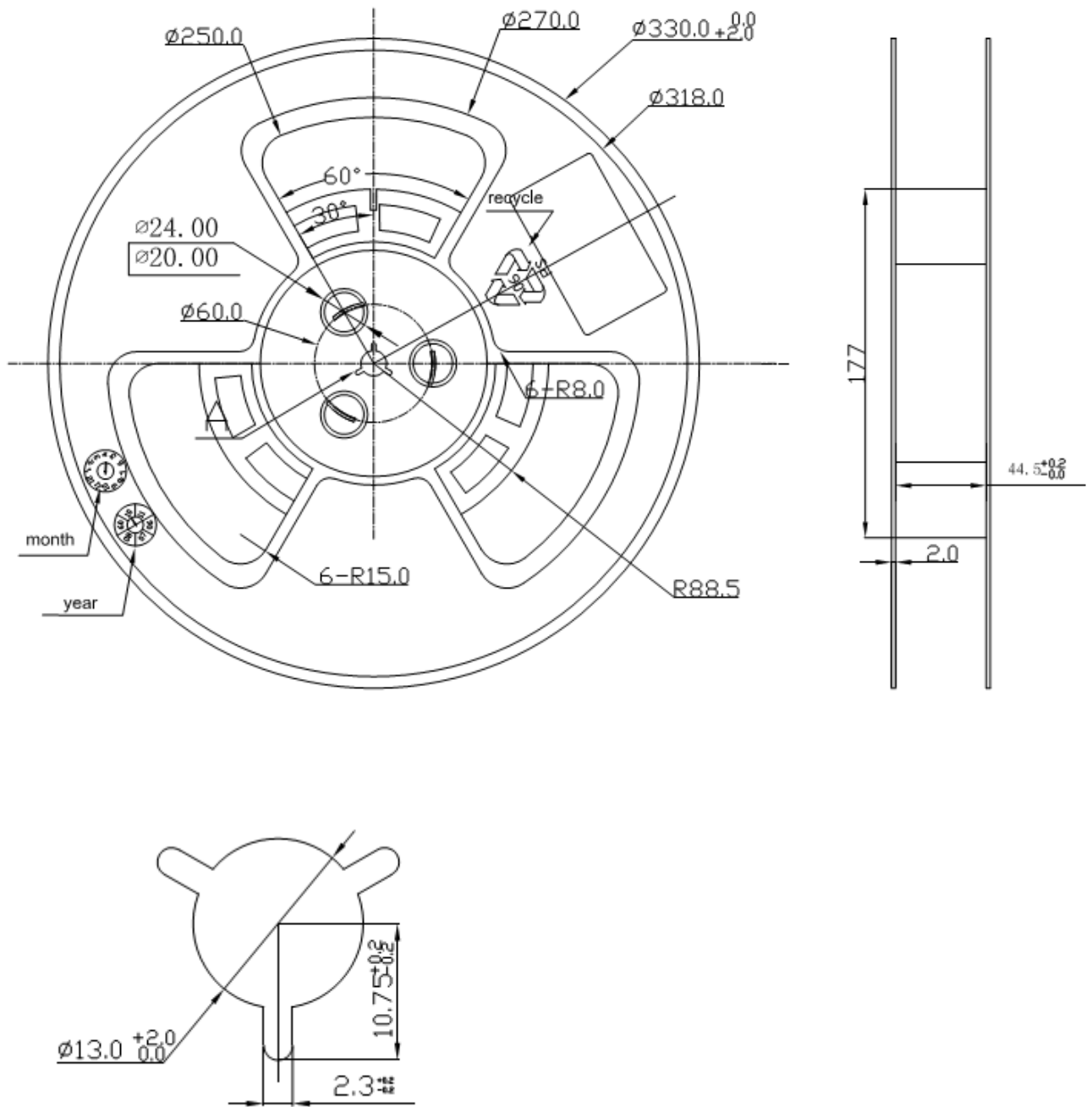
See figure for module positioning into the carrier.



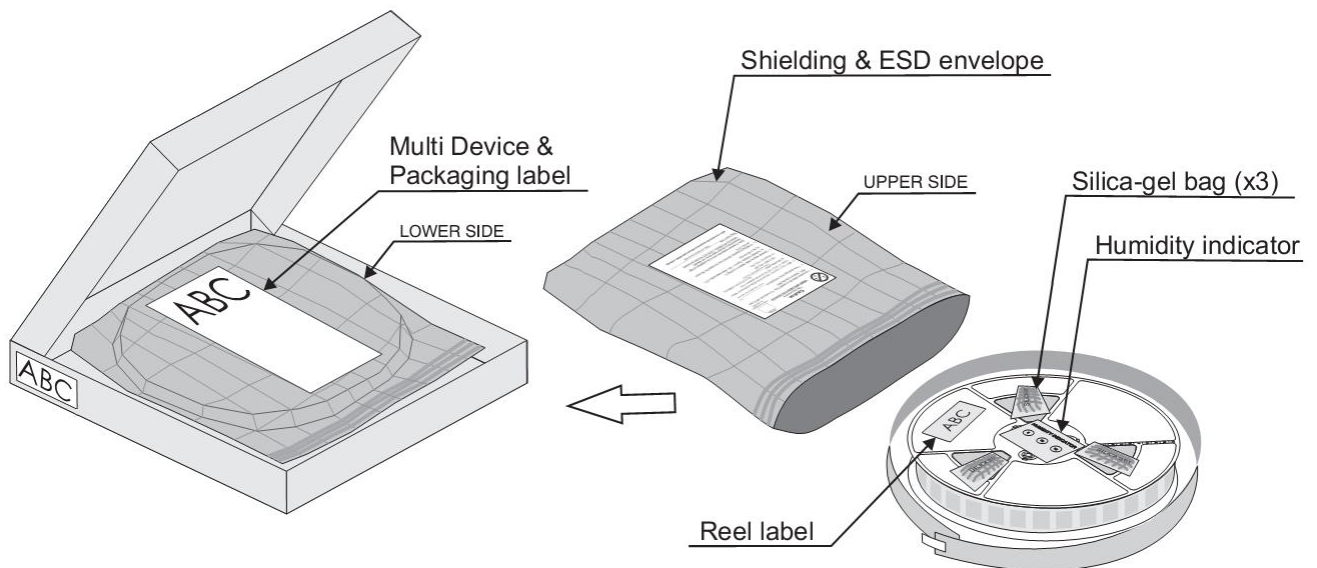
### 10.2.1 Carrier Tape Detail



10.2.2 Reel Detail



### 10.2.3 Reel Box Detail



## 10.3 Moisture sensitivity

The UE910 is a Moisture Sensitive Device level 3, in according with standard IPC/JEDEC J-STD-020, take care all the relatives requirements for using this kind of components.

Moreover, the customer has to take care of the following conditions:

- a) Calculated shelf life in sealed bag: 12 months at <math><40^{\circ}\text{C}</math> and <math><90\%</math> relative humidity (RH).
- b) Environmental condition during the production: <math>30^{\circ}\text{C}</math> / 60% RH according to IPC/JEDEC J-STD-033A paragraph 5.
- c) The maximum time between the opening of the sealed bag and the reflow process must be 168 hours if condition b) "IPC/JEDEC J-STD-033A paragraph 5.2" is respected
- d) Baking is required if conditions b) or c) are not respected
- e) Baking is required if the humidity indicator inside the bag indicates 10% RH or more



# 11 SAFETY RECOMMENDATIONS

## READ CAREFULLY

Be sure the use of this product is allowed in the country and in the environment required. The use of this product may be dangerous and has to be avoided in the following areas:

Where it can interfere with other electronic devices in environments such as hospitals, airports, aircrafts, etc

Where there is risk of explosion such as gasoline stations, oil refineries, etc

It is responsibility of the user to enforce the country regulation and the specific environment regulation.

Do not disassemble the product; any mark of tampering will compromise the warranty validity.

We recommend following the instructions of the hardware user guides for a correct wiring of the product. The product has to be supplied with a stabilized voltage source and the wiring has to be conforming to the security and fire prevention regulations.

The product has to be handled with care, avoiding any contact with the pins because electrostatic discharges may damage the product itself. Same cautions have to be taken for the SIM, checking carefully the instruction for its use. Do not insert or remove the SIM when the product is in power saving mode.

The system integrator is responsible of the functioning of the final product; therefore, care has to be taken to the external components of the module, as well as of any project or installation issue, because the risk of disturbing the GSM network or external devices or having impact on the security. Should there be any doubt, please refer to the technical documentation and the regulations in force.

Every module has to be equipped with a proper antenna with specific characteristics. The antenna has to be installed with care in order to avoid any interference with other electronic devices and has to guarantee a minimum distance from the body (20 cm). In case of this requirement cannot be satisfied, the system integrator has to assess the final product against the SAR regulation.

The European Community provides some Directives for the electronic equipments introduced on the market. All the relevant information's are available on the European Community website:

<http://europa.eu.int/comm/enterprise/rtte/dir99-5.htm>

The text of the Directive 99/05 regarding telecommunication equipments is available, while the applicable Directives (Low Voltage and EMC) are available at:

[http://europa.eu.int/comm/enterprise/electr\\_equipment/index\\_en.htm](http://europa.eu.int/comm/enterprise/electr_equipment/index_en.htm)

# 12 FCC/IC REGULATORY NOTICES

## Modification statement

Telit has not approved any changes or modifications to this device by the user. Any changes or modifications could void the user's authority to operate the equipment.

*Telit n'approuve aucune modification apportée à l'appareil par l'utilisateur, quelle qu'en soit la nature. Tout changement ou modification peuvent annuler le droit d'utilisation de l'appareil par l'utilisateur.*

## Interference statement

This device complies with Part 15 of the FCC Rules and Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

*Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.*

## Wireless notice

This equipment complies with FCC and IC radiation exposure limits set forth for an uncontrolled environment. The antenna should be installed and operated with minimum distance of 20 cm between the radiator and your body. Antenna gain must be below:

Frequency Band	Gain
Band II (1900 MHz)	9.01 dBi
Band V (850 MHz)	7.76 dBd

This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

*Cet appareil est conforme aux limites d'exposition aux rayonnements de la IC pour un environnement non contrôlé. L'antenne doit être installée de façon à garder une distance minimale de 20 centimètres entre la source de rayonnements et votre corps. Gain de l'antenne doit être ci-dessous:*

Bande de fréquence	Gain
Band II (1900 MHz)	9.01 dBi
Band V (850 MHz)	7.76 dBd

*L'émetteur ne doit pas être colocalisé ni fonctionner conjointement avec à autre antenne ou autre émetteur.*

### **FCC Class B digital device notice**

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

Reorient or relocate the receiving antenna.

Increase the separation between the equipment and receiver.

Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.

Consult the dealer or an experienced radio/TV technician for help.

### **Labelling Requirements for the Host device**

The host device shall be properly labelled to identify the modules within the host device. The certification label of the module shall be clearly visible at all times when installed in the host device, otherwise the host device must be labelled to display the FCC ID and IC of the module, preceded by the words "Contains transmitter module", or the word "Contains", or similar wording expressing the same meaning, as follows:

Contains FCC ID: RI7UE910N3

Contains IC: 5131A-UE910N3

*L'appareil hôte doit être étiqueté comme il faut pour permettre l'identification des modules qui s'y trouvent. L'étiquette de certification du module donné doit être posée sur l'appareil hôte à un endroit bien en vue en tout temps. En l'absence d'étiquette, l'appareil hôte doit porter une étiquette donnant le FCC ID et le IC du module, précédé des mots « Contient un module d'émission », du mot « Contient » ou d'une formulation similaire exprimant le même sens, comme suit :*

Contains FCC ID: RI7UE910N3

Contains IC: 5131A-UE910N3

**CAN ICES-3 (B) / NMB-3 (B)**

This Class B digital apparatus complies with Canadian ICES-003.

*Cet appareil numérique de classe B est conforme à la norme canadienne ICES-003.*

# 13 DOCUMENT HISTORY

## 13.1 Revisions

Revision	Date	Changes
0	2014-10-01	Preliminary Version
1	2015-01-08	Updated document format
2	2015-03-31	Added RX Sensitivity Added Third Party Rights Added FCC/IC Regulatory Notices Safety Recommendations Updated Tray Packaging Updated Chapter 4.2
3	2015-04-17	Updated Chapter 12
4	2016-11-30	Updated Chapter 3.1.1 LGA Pads Layout – updated pin B1 Updated Chapter 3.1 Pin Out – updated pin B1 (deleted from Reserved pin)

